

# DRV8711 Stepper Motor Controller IC

## 1 Features

- Pulse Width Modulation (PWM) Microstepping Motor Driver
  - Built-In 1/256-Step Microstepping Indexer
  - Drives External N-Channel MOSFETs
  - Optional STEP/DIR Pins
  - Optional PWM Control Interface for DC Motors
- Flexible Decay Modes, Including Automatic Mixed Decay Mode
- Stall Detection With Optional BEMF Output
- Highly Configurable SPI Serial Interface
- Internal Reference and Torque DAC
- 8-V to 52-V Operating Supply Voltage Range
- Scalable Output Current
- Thermally Enhanced Surface-Mount Package
- 5-V Regulator Capable of 10-mA Load
- Protection and Diagnostic Features
  - Overcurrent Protection (OCP)
  - Overtemperature Shutdown (OTS)
  - Undervoltage Lockout (UVLO)
  - Individual Fault Condition Indication Bits
  - Fault Condition Indication Pin

## 2 Applications

- Office Automation Machines
- Factory Automation
- Textile Machines
- Robotics

## 3 Description

The DRV8711 device is a stepper motor controller that uses external N-channel MOSFETs to drive a bipolar stepper motor or two brushed DC motors. A microstepping indexer is integrated, which is capable of step modes from full step to 1/256-step.

An ultra-smooth motion profile can be achieved using adaptive blanking time and various current decay modes, including an auto-mixed decay mode. Motor stall is reported with an optional back-EMF output.

A simple step/direction or PWM interface allows easy interfacing to controller circuits. A SPI serial interface is used to program the device operation. Output current (torque), step mode, decay mode, and stall detection functions are all programmable through a SPI serial interface.

Internal shutdown functions are provided for overcurrent protection, short-circuit protection, undervoltage lockout, and overtemperature. Fault conditions are indicated through a **FAULTn pin**, and each fault condition is reported through a dedicated bit through SPI.

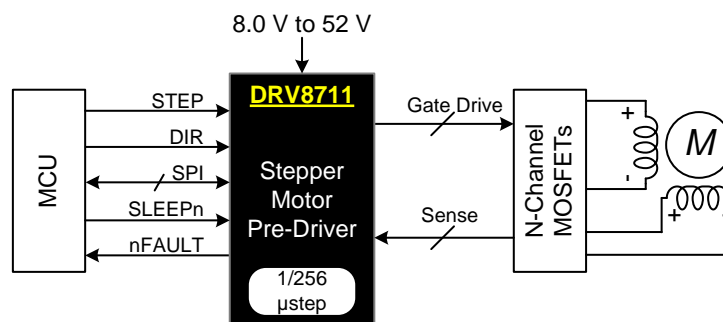
The DRV8711 is packaged in a PowerPAD™ 38-pin HTSSOP package with thermal pad (Eco-friendly: RoHS and no Sb/Br).

### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
DRV8711	HTSSOP (38)	9.70 mm × 4.40 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### Simplified Schematic



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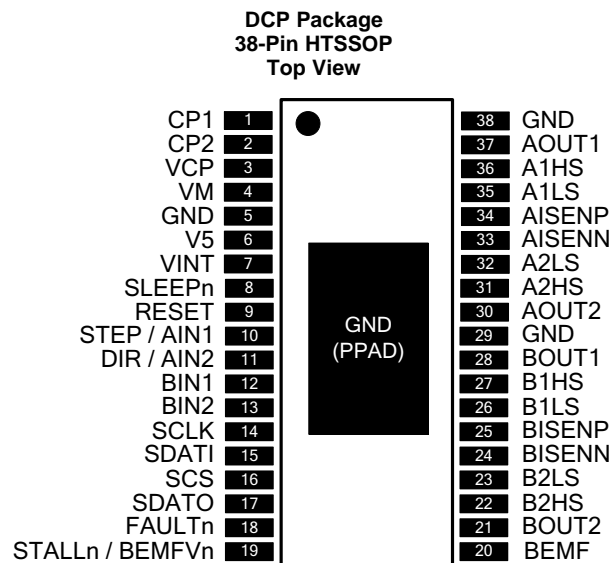
## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision D (January 2014) to Revision E	Page
<ul style="list-style-type: none"> <li>Added <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i>, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....</li> </ul>	<b>1</b>

Changes from Revision C (December 2013) to Revision D	Page
<ul style="list-style-type: none"> <li>Changed STATUS Register bit descriptions 3 through 5.....</li> </ul>	<b>28</b>

## 5 Pin Configuration and Functions



### Pin Functions

PIN		I/O <sup>(1)</sup>	DESCRIPTION	EXTERNAL COMPONENTS OR CONNECTIONS
NAME	NO.			
POWER AND GROUND				
GND	5, 29, 38, PPAD	—	Device ground	All pins must be connected to ground
VM	4	—	Bridge A power supply	Connect to motor supply voltage. Bypass to GND with a 0.01-μF ceramic capacitor plus a 100-μF electrolytic capacitor.
VINT	7	—	Internal logic supply voltage	Logic supply voltage. Bypass to GND with a 1-μF 6.3-V X7R ceramic capacitor.
V5	6	O	5-V regulator output	5-V linear regulator output. Bypass to GND with a 0.1-μF 10-V X7R ceramic capacitor.
CP1	1	IO	Charge pump flying capacitor	Connect a 0.1-μF X7R capacitor between CP1 and CP2. Voltage rating must be greater than applied VM voltage.
CP2	2	IO	Charge pump flying capacitor	
VCP	3	IO	High-side gate drive voltage	Connect a 1-μF 16-V X7R ceramic capacitor to VM
CONTROL				
SLEEPn	8	I	Sleep mode input	Logic high to enable device, logic low to enter low-power sleep mode
STEP/AIN1	10	I	Step input/Bridge A IN1	Indexer mode: Rising edge causes the indexer to move one step. External PWM mode: controls bridge A OUT1 Internal pulldown.
DIR/AIN2	11	I	Direction input/Bridge A IN2	Indexer mode: Level sets the direction of stepping. External PWM mode: controls bridge A OUT2 Internal pulldown.
BIN1	12	I	Bridge B IN1	Indexer mode: No function External PWM mode: controls bridge B OUT1 Internal pulldown.
BIN2	13	I	Bridge B IN2	Indexer mode: No function External PWM mode: controls bridge B OUT2 Internal pulldown.
RESET	9	I	Reset input	Active-high reset input initializes all internal logic and disables the H-bridge outputs. Internal pulldown.
SERIAL INTERFACE				
SCS	16	I	Serial chip select input	Active high to enable serial data transfer. Internal pulldown.
SCLK	14	I	Serial clock input	Rising edge clocks data into part for write operations. Falling edge clocks data out of part for read operations. Internal pulldown.
SDATI	15	I	Serial data input	Serial data input from controller. Internal pulldown.

(1) Directions: I = input, O = output, OZ = 3-state output, OD = open-drain output, IO = input/output

### Pin Functions (continued)

PIN		I/O <sup>(1)</sup>	DESCRIPTION	EXTERNAL COMPONENTS OR CONNECTIONS
NAME	NO.			
SDATO	17	O	Serial data output	Serial data output to controller. Open-drain output requires external pullup.
<b>STATUS</b>				
STALLn/ BEMFVn	19	OD	Stall/Back EMF valid	Internal stall detect mode: logic low when motor stall detected. External stall detect mode: Active low when valid back EMF measurement is ready. Open-drain output requires external pullup.
FAULTn	18	OD	Fault	Logic low when in fault condition. Open-drain output requires external pullup. Faults: OCP, PDF, OTS, UVLO
BEMF	20	O	Back EMF	Analog output voltage represents motor back EMF. Place a 1-nF low-leakage capacitor to ground on this pin.
<b>OUTPUTS</b>				
A1HS	36	O	Bridge A out 1 HS gate	Connect to gate of HS FET for bridge A out 1
AOUT1	37	I	Bridge A output 1	Connect to output node of external FETs of bridge A out 1
A1LS	35	O	Bridge A out 1 LS gate	Connect to gate of LS FET for bridge A out 1
A2HS	31	O	Bridge A out 2 HS gate	Connect to gate of HS FET for bridge A out 2
AOUT2	30	I	Bridge A output 2	Connect to output node of external FETs of bridge A out 2
A2LS	32	O	Bridge A out 2 LS gate	Connect to gate of LS FET for bridge A out 2
AISENP	34	I	Bridge A Isense + in	Connect to current sense resistor for bridge A
AISENN	33	I	Bridge A Isense – in	Connect to ground at current sense resistor for bridge A
B1HS	27	O	Bridge B out 1 HS gate	Connect to gate of HS FET for bridge B out 1
BOUT1	28	I	Bridge B output 1	Connect to output node of external FETs of bridge B out 1
B1LS	26	O	Bridge B out 1 LS gate	Connect to gate of LS FET for bridge B out 1
B2HS	22	O	Bridge B out 2 HS gate	Connect to gate of HS FET for bridge B out 2
BOUT2	21	I	Bridge B output 2	Connect to output node of external FETs of bridge B out 2
B2LS	23	O	Bridge B out 2 LS gate	Connect to gate of LS FET for bridge B out 2
BISENP	25	I	Bridge B Isense + in	Connect to current sense resistor for bridge B
BISENN	24	I	Bridge B Isense – in	Connect to ground at current sense resistor for bridge B

**Table 1. Critical Components**

PIN	NAME	COMPONENT
4	VM	100-μF electrolytic rated for VM voltage to GND 0.01-μF ceramic rated for VM voltage to GND
3	VCP	1-μF ceramic X7R rated 16 V to VCP
1, 2	CP1, CP2	0.1-μF rated for VM + 12 V between these pins
6	V5	0.1-μF ceramic X7R rated 6.3 V to GND
7	VINT	1-μF ceramic X7R rated 6.3 V to GND
17	SDATO	Requires external pullup to logic supply
18	FAULTn	Requires external pullup to logic supply
19	STALLn/BEMFVn	Requires external pullup to logic supply
20	BEMF	1-nF low-leakage capacitor to GND

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)(2) (3)</sup>

	MIN	MAX	UNIT
Power supply voltage	–0.6	60	V
Charge pump voltage (CP1, CP2, VCP)	–0.6	12	V
5-V regulator voltage (V5)	–0.6	5.5	V
Internal regulator voltage (VINT)	–0.6	2	V
Digital pin voltage (SLEEPn, RESET, STEP/AIN1, DIR/AIN2, BIN1, BIN2, SCS, SCLK, SDAT1, SDAT0, FAULTn, STALLn/BEMFVn)	–0.6	5.5	V
High-side gate drive pin voltage (A1HS, A2HS, B1HS, B2HS)	–0.6	12	V
Low-side gate drive pin voltage (A1LS, A2LS, B1LS, B2LS)	–0.6	12	V
Phase node pin voltage (AOUT1, AOUT2, BOUT1, BOUT2)	–0.6	VM	V
ISENSEx pin voltage (AISENP, AISENN, BISENP, BISENN)	–0.7	0.7	V
BEMF pin voltage (BEMF)	–0.6	5.5	V
Operating virtual junction temperature, T <sub>J</sub>	–40	150	°C
Storage temperature, T <sub>stg</sub>	–60	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.
- (3) Power dissipation and thermal limits must be observed.

### 6.2 ESD Ratings

	VALUE	UNIT
V <sub>(ESD)</sub> Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	±4000
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±1500

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
V <sub>M</sub> Motor power supply voltage range	8		52	V
I <sub>VS</sub> V5 external load current	0		10	mA
T <sub>A</sub> Operating ambient temperature range	–40		85	°C

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		DRV8711	UNIT
		DCP (HTSSOP)	
		38 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	32.7	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	17.2	
R <sub>θJB</sub>	Junction-to-board thermal resistance	14.3	
ψ <sub>JT</sub>	Junction-to-top characterization parameter	0.5	
ψ <sub>JB</sub>	Junction-to-board characterization parameter	14.1	
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	0.9	

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLIES						
I <sub>VM</sub>	VM operating supply current	VM = 24 V		17	20	mA
I <sub>VMQ</sub>	VM sleep mode supply current	VM = 24 V, SLEEPn = 0, T <sub>A</sub> = 25°C		65	98	µA
V <sub>UVLO</sub>	VM undervoltage lockout voltage	VM rising		7.1	8	V
		VM falling		6.3		
INTERNAL LINEAR REGULATORS						
V <sub>5</sub>	V5 output voltage	VM ≥ 12 V, I <sub>OUT</sub> = 1 mA – 10 mA	4.8	5	5.2	V
V <sub>INT</sub>	VINT voltage	No external load – reference only	1.7	1.8	1.9	V
LOGIC-LEVEL INPUTS						
V <sub>IL</sub>	Input low voltage				0.8	V
V <sub>IH</sub>	Input high voltage		1.5			V
V <sub>HYS</sub>	Input hysteresis voltage			300		mV
I <sub>IL</sub>	Input low current	V <sub>IN</sub> = 0 V	–5		5	µA
I <sub>IH</sub>	Input high current	V <sub>IN</sub> = 5 V	30	50	70	µA
SDATA0, STALLn, FAULTn OUTPUTS (OPEN-DRAIN OUTPUTS)						
V <sub>OL</sub>	Output low voltage	I <sub>O</sub> = 5 mA			0.5	V
I <sub>OH</sub>	Output high leakage current	V <sub>O</sub> = 3.3 V			1	µA
MOSFET DRIVERS						
V <sub>OUTH</sub>	High-side gate drive output voltage	VM = 24 V, I <sub>O</sub> = 100 µA		VM+10		V
V <sub>OUTL</sub>	Low-side gate drive output voltage	VM = 24 V, I <sub>O</sub> = 100 µA		10		V
t <sub>DEAD</sub>	Output dead time digital delay (dead time is enforced in analog circuits)	DTIME = 00		400		ns
		DTIME = 01		450		
		DTIME = 10		650		
		DTIME = 11		850		
I <sub>OUTH</sub>	Peak output current gate drive (source)	IDRIVEP = 00		50		mA
		IDRIVEP = 01		100		
		IDRIVEP = 10		150		
		IDRIVEP = 11		200		
I <sub>OUTI</sub>	Peak output current gate drive (sink)	IDRIVEN = 00		100		mA
		IDRIVEN = 01		150		
		IDRIVEN = 10		200		
		IDRIVEN = 11		400		
t <sub>DRIVE</sub>	Peak current drive time (source)	TDRIVEP = 00		250		ns
		TDRIVEP = 01		500		
		TDRIVEP = 10		1000		
		TDRIVEP = 11		2000		
t <sub>DRIVE</sub>	Peak current drive time (sink)	TDRIVEN = 00		250		ns
		TDRIVEN = 01		500		
		TDRIVEN = 10		1000		
		TDRIVEN = 11		2000		
MOTOR DRIVER						
t <sub>OFF</sub>	PWM off time adjustment range	Set by TOFF register	0.5		128	µs
t <sub>BLANK</sub>	Current sense blanking time	Set by TBLANK register	0.5		5.12	µs

## Electrical Characteristics (continued)

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>PROTECTION CIRCUITS</b>						
$V_{OCP}$	Overcurrent protection trip level (Voltage drop across external FET)	OCPH = 00	160	250	320	mV
		OCPH = 01	380	500	580	
		OCPH = 10	620	750	850	
		OCPH = 11	840	1000	1200	
$t_{TSD}$	Thermal shutdown temperature <sup>(1)</sup>	Die temperature	150	160	180	°C
$t_{HYS}$	Thermal shutdown hysteresis			20		°C
<b>CURRENT SENSE AMPLIFIERS</b>						
$A_V$	Gain	ISGAIN = 00		5		V/V
		ISGAIN = 01		10		
		ISGAIN = 10		20		
		ISGAIN = 11		40		
$t_{SET}$	Settling time (to $\pm 1\%$ )	ISGAIN = 00, $\Delta V_{IN} = 400$ mV		150		ns
		ISGAIN = 01, $\Delta V_{IN} = 200$ mV		300		
		ISGAIN = 10, $\Delta V_{IN} = 100$ mV		600		
		ISGAIN = 11, $\Delta V_{IN} = 50$ mV		1.2		$\mu$ s
$V_{OFS}$	Offset voltage	ISGAIN = 00, input shorted			4	mV
$V_{IN}$	Input differential voltage range		–600		600	mV
<b>CURRENT CONTROL DACs</b>						
	Resolution			256		steps
	Full-scale step response	10% to 90%			5	$\mu$ s
$V_{REF}$	Full-scale (reference) voltage		2.50	2.75	3	V

(1) Not tested in production; ensured by design.

## 6.6 SPI Interface Timing Requirements

over operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

NO.		MIN	TYP	MAX	UNIT
1	$t_{CYC}$ Clock cycle time	250			ns
2	$t_{CLKH}$ Clock high time	25			ns
3	$t_{CLKL}$ Clock low time	25			ns
4	$t_{SU(SDATI)}$ Setup time, SDATI to SCLK	5			ns
5	$t_{H(SDATI)}$ Hold time, SDATI to SCLK	1			ns
6	$t_{SU(SCS)}$ Setup time, SCS to SCLK	5			ns
7	$t_{H(SCS)}$ Hold time, SCS to SCLK	1			ns
8	$t_{L(SCS)}$ Inactive time, SCS (between writes and reads)	100			ns
9	$t_{D(SDATO)}$ Delay time, SCLK to SDATO (during read)			10	ns
	$t_{SLEEP}$ Wake time (SLEEPn inactive to high-side gate drive enabled)			1	ms
	$t_{RESET}$ Delay from power up or RESETn high until serial interface functional			10	$\mu$ s

## 6.7 Indexer Timing Requirements

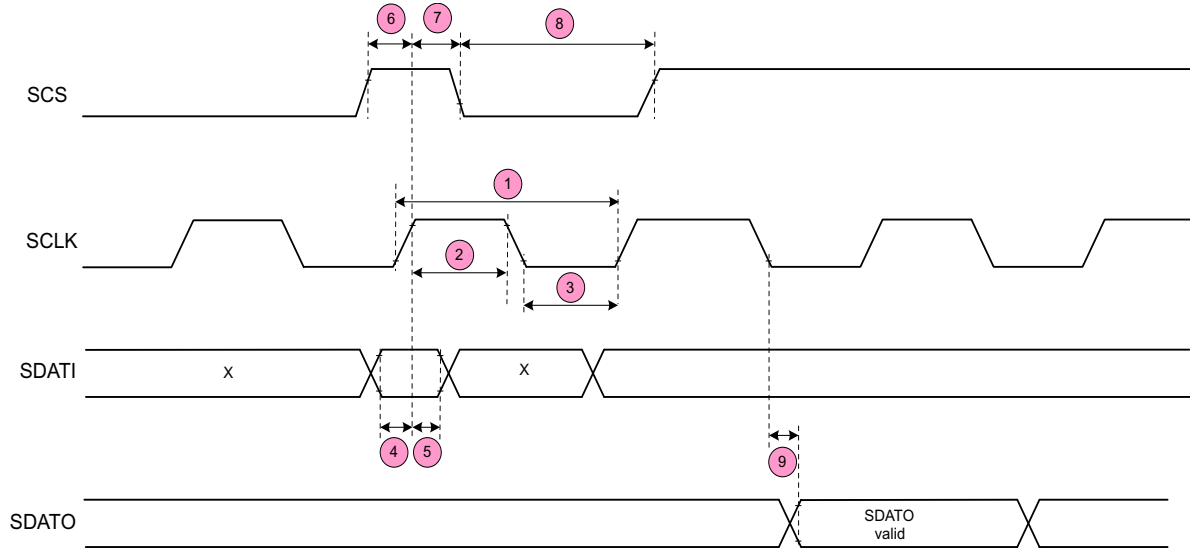
over operating free-air temperature range (unless otherwise noted) (see [Figure 2](#))

NO.		MIN	TYP	MAX	UNIT
1	$f_{STEP}$ Step frequency			250	kHz
2	$t_{WH(STEP)}$ Pulse duration, STEP high	1.9			$\mu$ s
3	$t_{WL(STEP)}$ Pulse duration, STEP low	1.9			$\mu$ s
4	$t_{SU(STEP)}$ Setup time, command to STEP rising	200			ns

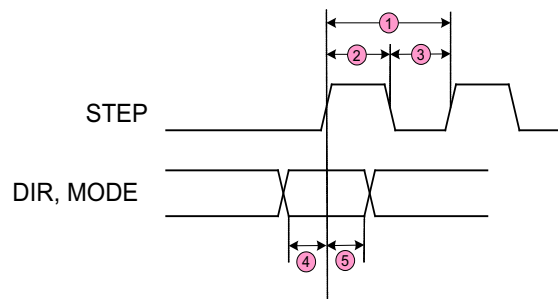
## Indexer Timing Requirements (continued)

over operating free-air temperature range (unless otherwise noted) (see [Figure 2](#))

NO.		MIN	TYP	MAX	UNIT
5	$t_{H(STEP)}$ Hold time, command to STEP rising	200			ns



**Figure 1. SPI Interface Timing**



**Figure 2. Indexer Timing**



## 6.8 Typical Characteristics

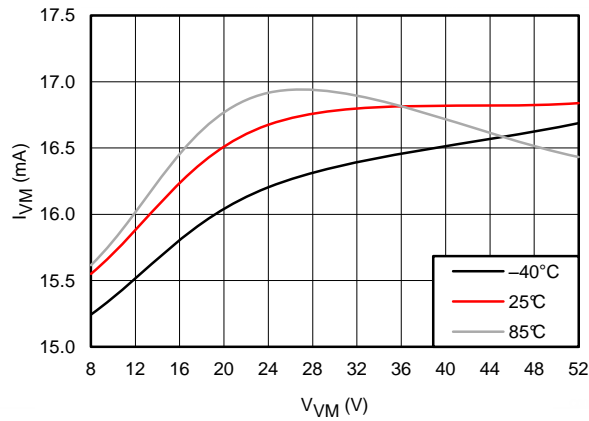


Figure 3. Operating Current

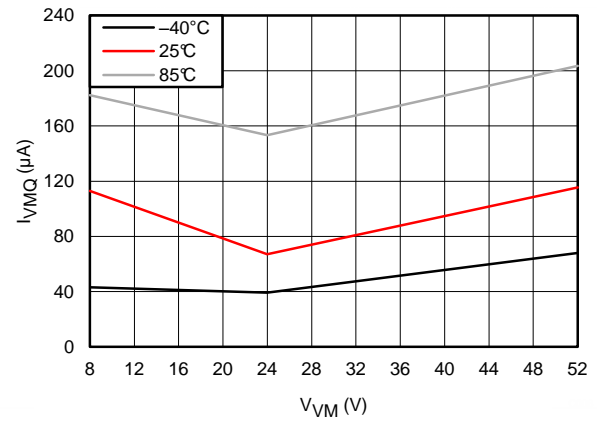


Figure 4. Sleep Current

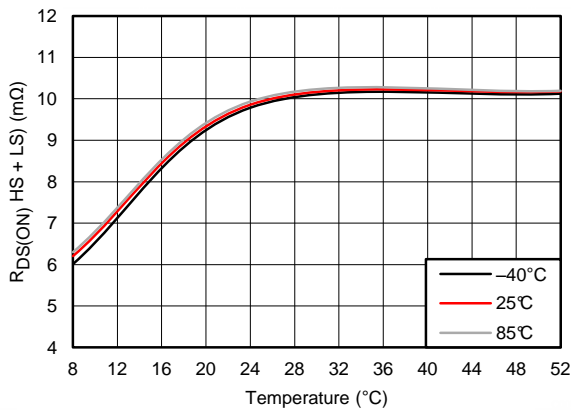


Figure 5. VCP Minus VM

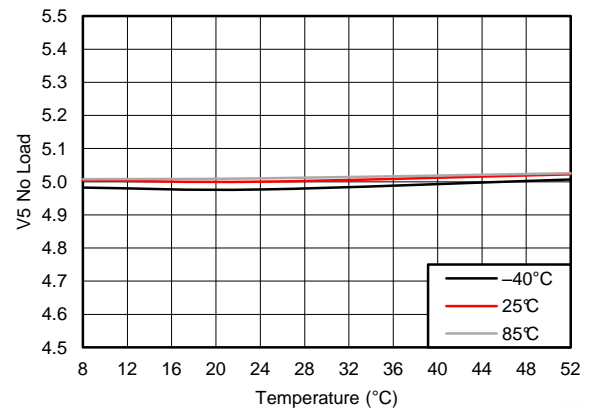


Figure 6. V5 No Load

## 7 Detailed Description

### 7.1 Overview

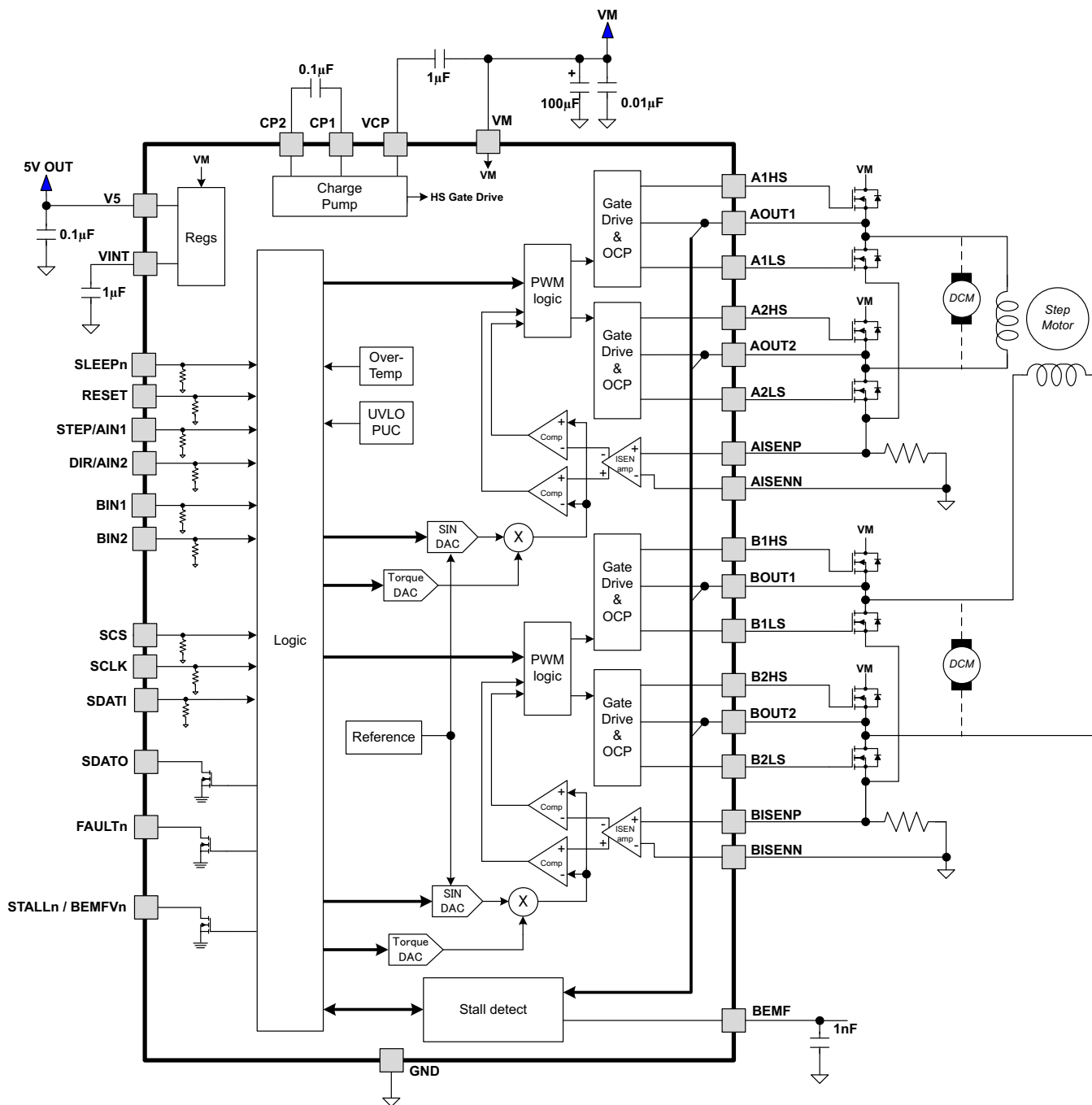
The DRV8711 device is a stepper motor controller that uses external N-channel MOSFETs to drive a bipolar stepper motor or two brushed DC motors. A microstepping indexer is integrated, which is capable of step modes from full step to 1/256-step.

An ultra-smooth motion profile can be achieved using adaptive blanking time, adjustable decay times, and various current decay modes, including an auto-mixed decay mode. When microstepping, motor stall can be reported with an optional back-EMF output.

A simple step/direction or PWM interface allows easy interfacing to controller circuits. A SPI serial interface is used to program the device operation. Output current (torque), step mode, decay mode, and stall detection functions are all programmable through a SPI serial interface.

Internal shutdown functions are provided for overcurrent protection, short-circuit protection, undervoltage lockout, and overtemperature. Fault conditions are indicated through a FAULTn pin, and each fault condition is reported through a dedicated bit through SPI.

## 7.2 Functional Block Diagram



## 7.3 Feature Description

### 7.3.1 PWM Motor Drivers

The DRV8711 contains two H-bridge motor predrivers with current control PWM circuitry. More detailed descriptions of the subblocks are described in the following sections.

## Feature Description (continued)

### 7.3.2 Direct PWM Input Mode

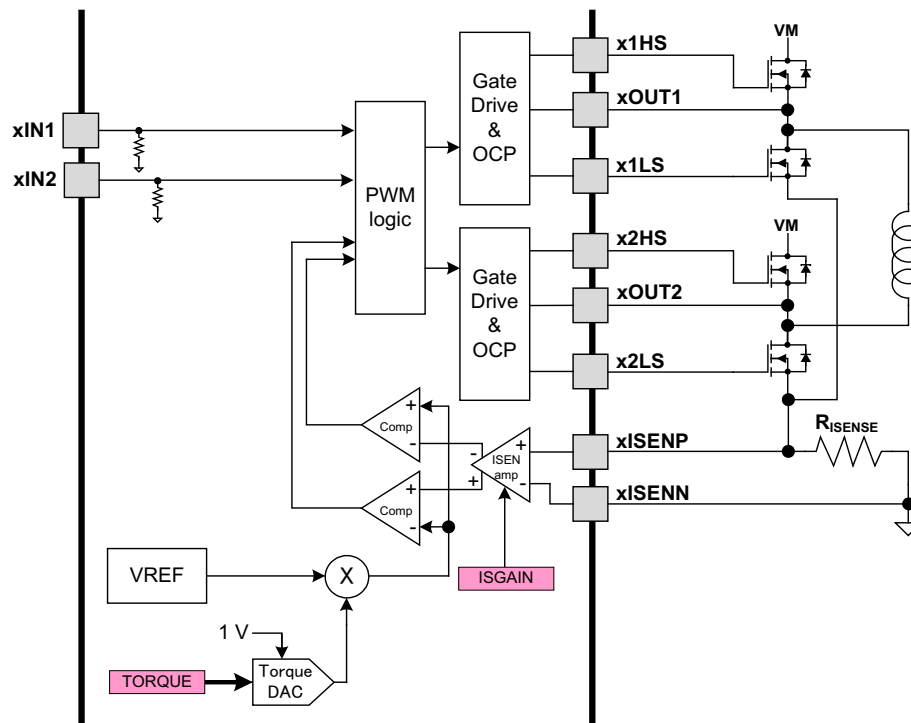
Direct PWM mode is selected by setting the PWMMODE bit in the OFF register. In direct PWM input mode, the AIN1, AIN2, BIN1, and BIN2 directly control the state of the output drivers. This allows for driving up to two brushed DC motors. The logic is shown in [Table 2](#):

**Table 2. Direct PWM Input Mode Logic**

xIN1	xIN2	xOUT1	xOUT2	OPERATION
0	0	Z	Z	Asynchronous Fast Decay
0	1	L	H	Reverse Drive
1	0	H	L	Forward Drive
1	1	L	L	Slow Decay

If mixed or auto-mixed decay modes are used, they will apply to every cycle, because current change information is not available.

In direct PWM mode, the current control circuitry is still active. The full-scale VREF is set to 2.75 V. The TORQUE register may be used to scale this value, and the ISEN sense amp gain may still be set using the ISGAIN bits of the CTRL register.



**Figure 7. Direct PWM Input Mode**

The current through the motor windings is regulated by an adjustable fixed-off-time PWM current regulation circuit. When an H-bridge is enabled, current rises through the winding at a rate dependent on the DC voltage and inductance of the winding and the magnitude of the back EMF present. Once the current hits the current chopping threshold, the bridge disables the current for a fixed period of time, which is programmable between 500 nS and 128  $\mu$ S by writing to the TOFF bits in the OFF register. After the off time expires, the bridge is re-enabled, starting another PWM cycle.

The chopping current is set by a comparator which compares the voltage across a current sense resistor connected to the xISENx pins, multiplied by the gain of the current sense amplifier, with a reference voltage. The current sense amplifier is programmable in the CTRL register.

When driving in PWM mode, the chopping current is calculated as follows:

$$I_{CHOP} = \frac{2.75V \bullet TORQUE}{256 \bullet ISGAIN \bullet R_{ISENSE}} \quad (1)$$

Where TORQUE is the setting of the TORQUE bits, and ISGAIN is the programmed gain of the ISENSE amplifiers (5, 10, 20, or 40).

### 7.3.3 Microstepping Indexer

Built-in indexer logic in the DRV8711 allows a number of different stepping configurations. The MODE bits in the CTRL register are used to configure the stepping format as shown in [Table 3](#).

**Table 3. Microstepping Indexer Logic**

MODE3	MODE2	MODE1	MODE0	STEP MODE
0	0	0	0	Full-step (2-phase excitation) with 71% current
0	0	0	1	1/2 step
0	0	1	0	1/4 step
0	0	1	1	1/8 step
0	1	0	0	1/16 step
0	1	0	1	1/32 step
0	1	1	0	1/64 step
0	1	1	1	1/128 step
1	0	0	0	1/256 step

Table 4 shows the relative current and step directions for full-step through 1/8-step operation. Higher microstepping resolutions follow the same pattern. The AOUT current is the sine of the electrical angle; BOUT current is the cosine of the electrical angle.

The reset state is 45°. This state is entered at power up or application of RESETn. This is shown in Table 4 by cells shaded in yellow.

**Table 4. Step Directions**

FULL STEP	1/2 STEP	1/4 STEP	1/8 STEP	AOUT CURRENT (% FULL-SCALE)	BOUT CURRENT (% FULL-SCALE)	ELECTRICAL ANGLE (DEGREES)
	1	1	1	0	100	0
			2	20	98	11.325
		2	3	38	92	22.5
			4	56	83	33.75
1	2	3	5	71	71	45 (home state)
			6	83	56	56.25
		4	7	92	38	67.5
			8	98	20	78.75
	3	5	9	100	0	90
			10	98	–20	101.25
		6	11	92	–38	112.5
			12	83	–56	123.75
2	4	7	13	71	–71	135
			14	56	–83	146.25
		8	15	38	–92	157.5
			16	20	–98	168.75
	5	9	17	0	–100	180
			18	–20	–98	191.25
		10	19	–38	–92	202.5
			20	–56	–83	213.75
3	6	11	21	–71	–71	225
			22	–83	–56	236.25
		12	23	–92	–38	247.5
			24	–98	–20	258.75
	7	13	25	–100	0	270
			26	–98	20	281.25
		14	27	–92	38	292.5
			28	–83	56	303.75
4	8	15	29	–71	71	315
			30	–56	83	326.25
		16	31	–38	92	337.5
			32	–20	98	348.75

At each rising edge of the STEP input, or each time a 1 is written to the RSTEP bit in the CTRL register, the indexer travels to the next state in the table. The direction is shown with the DIR pin high and the RDIR bit in the CTRL register set to 0, or the DIR pin low and the RDIR bit set to 1. If the DIR pin is low with the RDIR bit 0, or the DIR pin is high with the RDIR bit 1, the sequence is reversed. Positive current is defined as xOUT1 = positive with respect to xOUT2.

If the step mode is changed while stepping, the indexer will advance to the next valid state for the new MODE setting at the rising edge of STEP.

### 7.3.4 Current Regulation

The current through the motor windings is regulated by an adjustable fixed-off-time PWM current regulation circuit. When an H-bridge is enabled, current rises through the winding at a rate dependent on the DC voltage and inductance of the winding and the magnitude of the back EMF present. Once the current hits the current chopping threshold, the bridge disables the current for a fixed period of time, which is programmable between 500 nS and 128  $\mu$ S by writing to the TOFF bits in the OFF register. After the off time expires, the bridge is re-enabled, starting another PWM cycle.

In stepping motors, current regulation is used to vary the current in the two windings in a sinusoidal fashion to provide smooth motion.

The PWM chopping current is set by a comparator which compares the voltage across a current sense resistor connected to the xISENx pins, multiplied by the gain of the current sense amplifier, with a reference voltage. The current sense amplifier is programmable in the CTRL register.

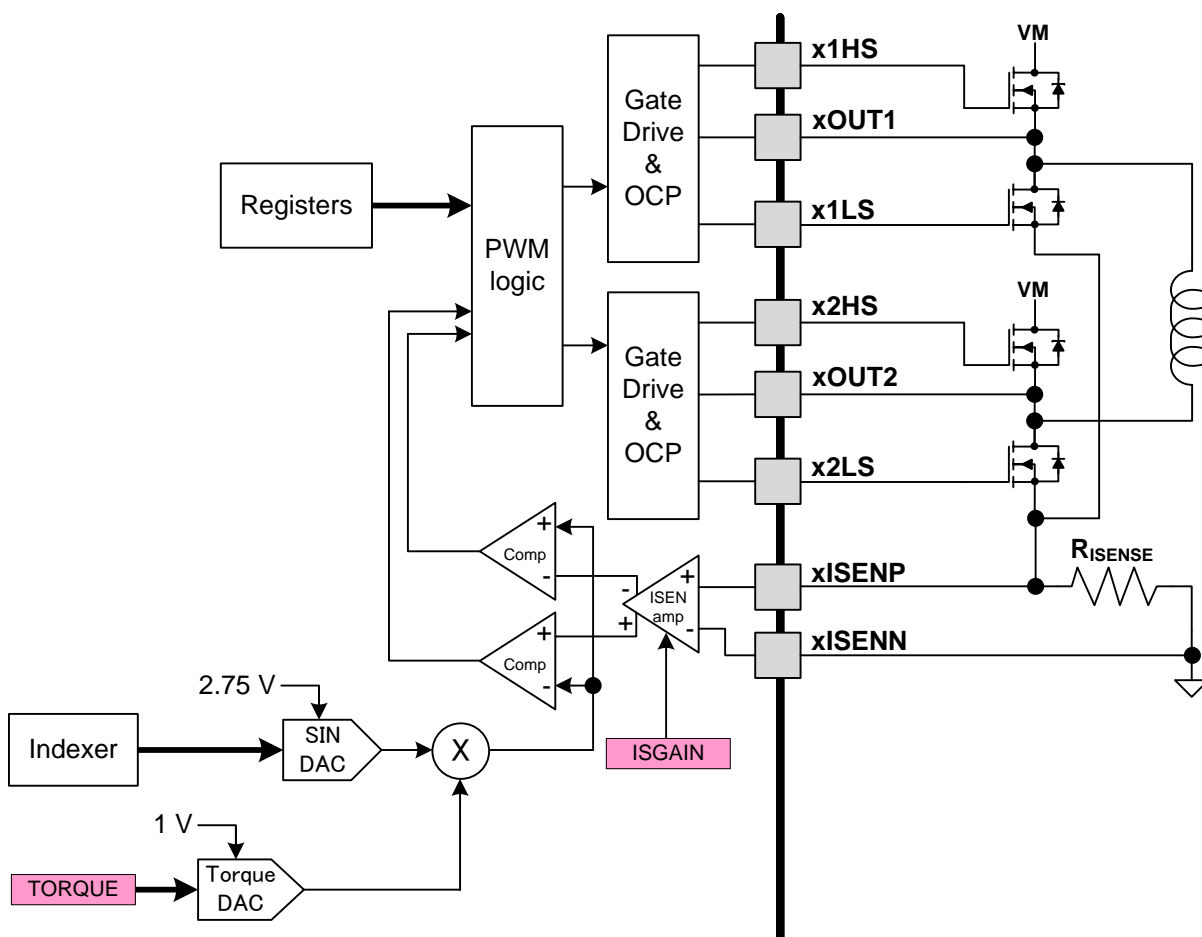


Figure 8. PWM Chopping Current

To generate the reference voltage for the current chopping comparator, the output of a sine lookup table is multiplied by the value of the bits in the TORQUE register. This result is applied to a sine-weighted DAC, whose full-scale output voltage is 2.75 V.

Therefore, the full-scale (100%) chopping current is calculated as follows:

$$I_{FS} = \frac{2.75V \bullet \text{TORQUE}}{256 \bullet \text{ISGAIN} \bullet R_{\text{ISENSE}}}$$

where

- TORQUE is the setting of the TORQUE bits
- ISGAIN is the programmed gain of the ISENSE amplifiers (5, 10, 20, or 40)

(2)

Example:

If a 0.1-Ω sense resistor is used, ISGAIN is set to 0 (gain of 5), and TORQUE is set to 255, the full-scale (100%) chopping current will be  $(2.75 \text{ V} \cdot 255) / (256 \cdot 5 \cdot 0.1 \text{ } \Omega) = 5.5 \text{ A}$ .

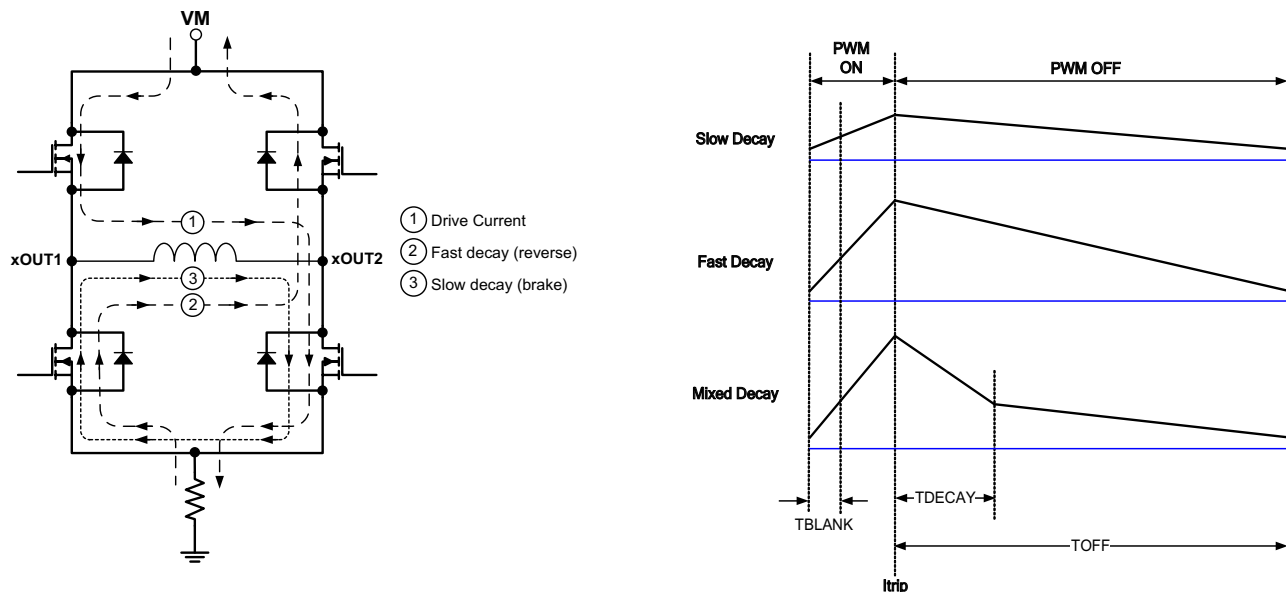
### 7.3.5 Decay Modes

During PWM current chopping, the H-bridge is enabled to drive through the motor winding until the PWM current chopping threshold is reached. This is shown in Figure 9, Item 1. The current flow direction shown indicates positive current flow in the step table below.

Once the chopping current threshold is reached, the H-bridge can operate in two different states, fast decay or slow decay.

In fast decay mode, once the PWM chopping current level has been reached, the H-bridge reverses state to allow winding current to flow in a reverse direction. The opposite FETs are turned on; as the winding current approaches zero, the bridge is disabled to prevent any reverse current flow. Fast decay mode is shown in Figure 9, item 2.

In slow decay mode, winding current is recirculated by enabling both of the low-side FETs in the bridge. This is shown in Figure 9, Item 3.



**Figure 9. Decay Modes**

The DRV8711 supports fast decay and slow decay modes in both indexer and direct PWM modes. In addition, in indexer mode only, it supports fixed mixed decay and auto-mixed decay modes. Decay mode is selected by the DECMOD bits in the DECAY register.

Mixed decay mode begins as fast decay, but after a programmable period of time (set by the TDECAY bits in the DECAY register) switches to slow decay mode for the remainder of the fixed off time. Even if mixed decay is selected, if the current is increasing or remaining the same (per the step table), then slow decay is used.

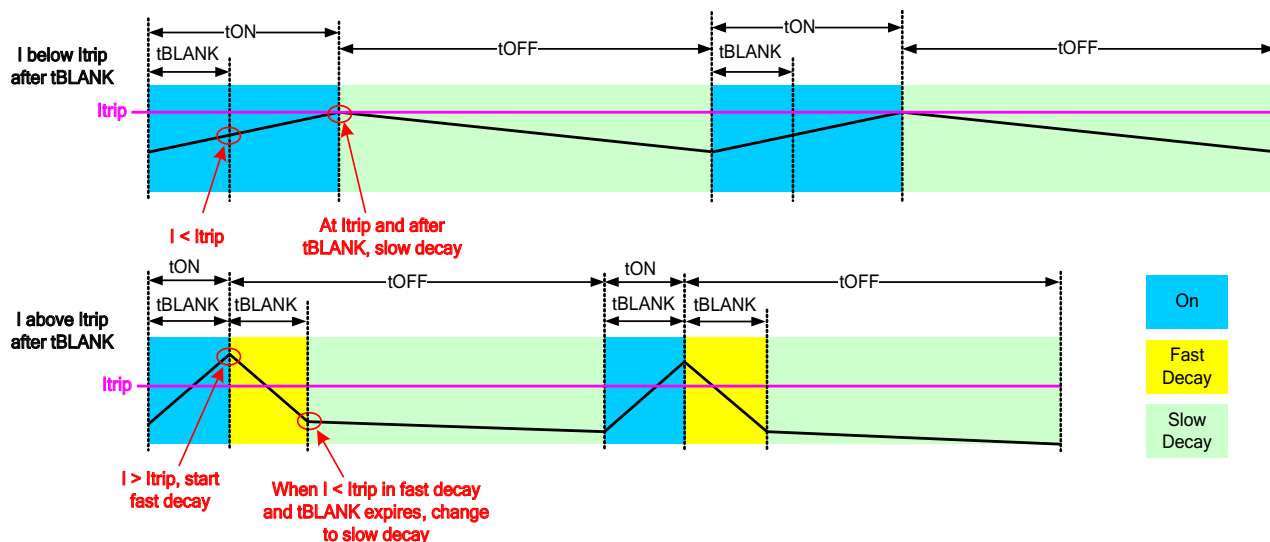


Auto-mixed decay mode samples the current level at the end of the blanking time, and if the current is above the  $I_{trip}$  threshold, immediately changes the H-bridge to fast decay. During fast decay, the (negative) current is monitored, and when it falls below the  $I_{trip}$  threshold (and another blanking time has passed), the bridge is switched to slow decay. Once the fixed off time expires, a new cycle is started.

If the bridge is turned on and at the end of  $TBLANK$  the current is below the  $I_{trip}$  threshold, the bridge remains on until the current reaches  $I_{trip}$ . Then slow decay is entered for the fixed off time, and a new cycle begins.

See [Figure 10](#) and [Figure 11](#).

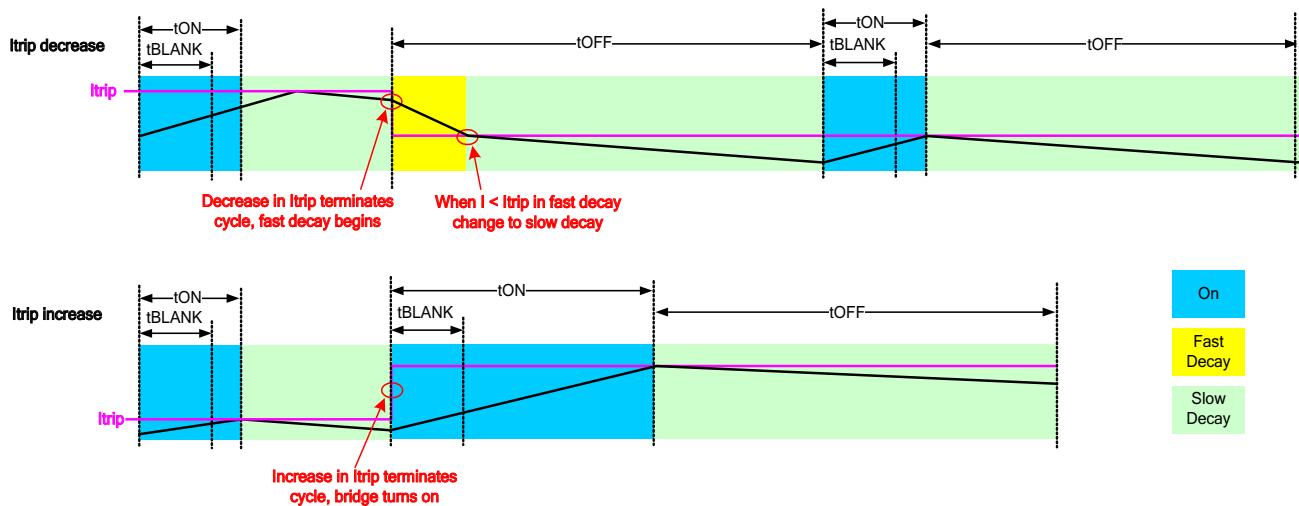
The upper waveform shows the behavior if  $I < I_{trip}$  at the end of  $tBLANK$ . At slow motor speeds, where back EMF is not significant, the current increase during the ON phase is the same magnitude as the current decrease in fast decay, because both times are controlled by  $tBLANK$ , and the rate of change is the same (full  $V_M$  is applied to the load inductance in both cases, but in opposite directions). In this case, the current will gradually be driven down until the peak current is just hitting  $I_{trip}$  at the end of the blanking time, after which some cycles will be slow decay, and some will be mixed decay.



**Figure 10.  $I < I_{trip}$  at the End of  $tBLANK$**

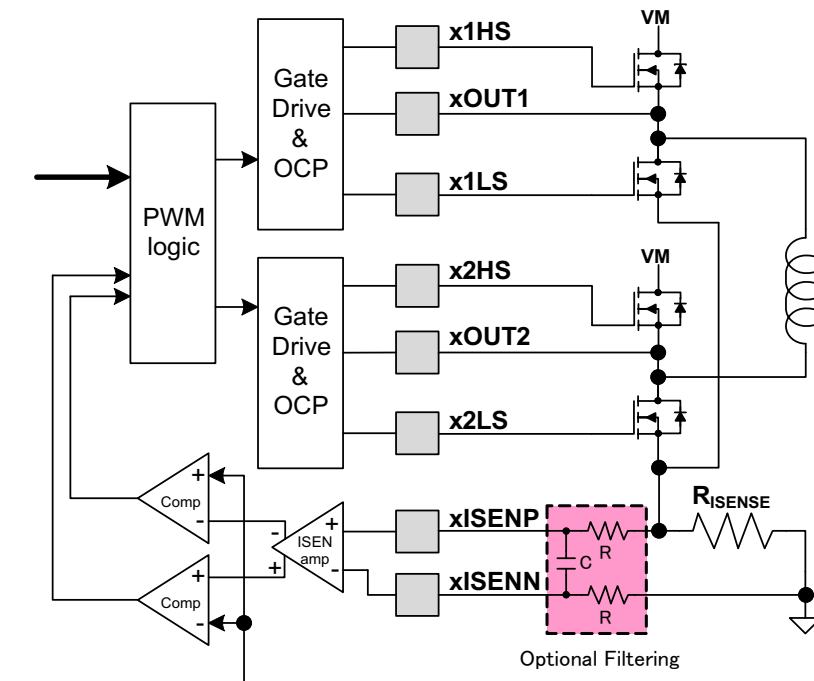
If the  $I_{trip}$  level changes during a PWM cycle (in response to a step command to the indexer), the current cycle is immediately terminated, and a new cycle is begun. Refer to the drawing below.

If the  $I_{trip}$  level has increased, the H-bridge will immediately turn on; if the  $I_{trip}$  level has decreased, fast decay mode is begun immediately. The top waveform shows what happens when the  $I_{trip}$  threshold decreases during a PWM cycle. The lower  $I_{trip}$  level results in the current being above the  $I_{trip}$  threshold at the end of  $tBLANK$  on the following cycle. Fast decay is entered until the current is driven below the  $I_{trip}$  threshold.



### Figure 11. Itrip Level Changing During a PWM Cycle

To accurately detect zero current, an internal offset has been intentionally placed in the zero current detection circuit. If an external filter is placed on the current sense resistor to the xISENN and xISENP pins, symmetry must be maintained. This means that any resistance between the bottom of the R<sub>ISENSE</sub> resistor and xISENN must be matched by the same resistor value (1% tolerance) between the top of the R<sub>ISENSE</sub> resistor and xISENP. Ensure a maximum resistance of 500  $\Omega$ . The capacitor value should be chosen such that the RC time constant is between 50 ns and 60 ns. Any external filtering on these pins is optional and not required for operation.



### Figure 12. Optional Filtering Between R<sub>ISENSE</sub> and xINSENx

### 7.3.6 Blanking Time

After the current is enabled in an H-bridge, the voltage on the ISEN pin is ignored for a period of time before enabling the current sense circuitry. This blanking time is adjustable from 1  $\mu$ S to 5.12  $\mu$ s, in 20 ns increments, by setting the TBLANK bits in the BLANK register. Note that the blanking time also sets the minimum on time of the PWM.

The same blanking time is applied to the fast decay period in auto decay mode. The PWM will ignore any transitions on  $I_{trip}$  after entering fast decay mode, until the blanking time has expired.

To provide better current control at very low current steps, an adaptive blanking time mode can be enabled by setting the ABT bit in the BLANK register. If ABT is set, at current levels below 30% of full scale current (as determined by the step table), the blanking time (so also the minimum on time) is cut in half, to 50% of the value programmed by the TBLANK bits.

For higher degrees of micro-stepping, TI recommends enabling ABT bit for better current regulation.

### 7.3.7 Predrivers

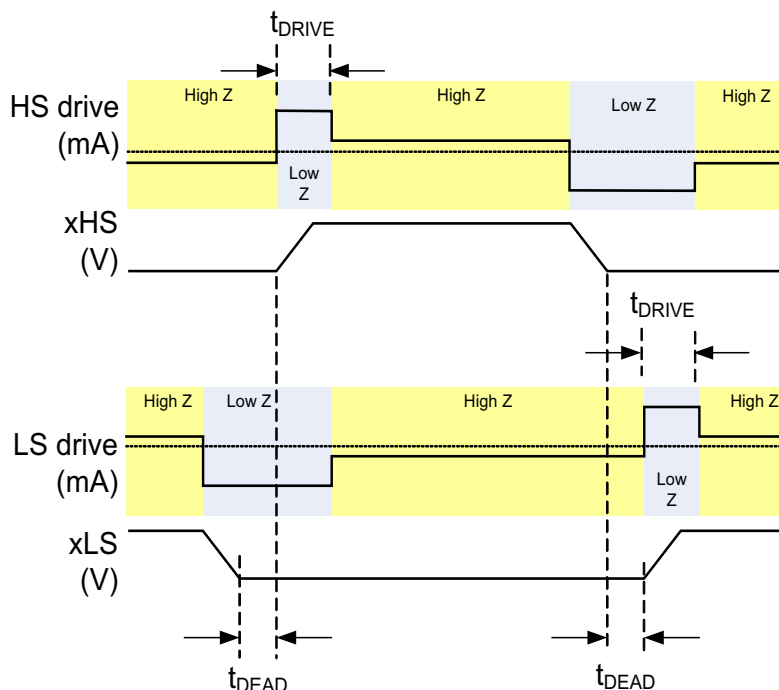
An internal charge pump circuit and predrivers inside the DRV8711 directly drive N-channel MOSFETs, which drive the motor current.

The peak drive current of the predrivers is adjustable by setting the bits in the DRIVE register. Peak source currents may be set to 50 mA, 100 mA, 150 mA, or 200 mA. The peak sink current is approximately 2x the peak source current. Adjusting the peak current will change the output slew rate, which also depends on the FET input capacitance and gate charge.

When changing the state of the output, the peak current is applied for a short period of time ( $t_{DRIVE}$ ), to charge the gate capacitance. After this time, a weak current source is used to keep the gate at the desired state. When selecting the gate drive strength for a given external FET, the selected current must be high enough to fully charge and discharge the gate during the time when driven at full current, or excessive power will be dissipated in the FET.

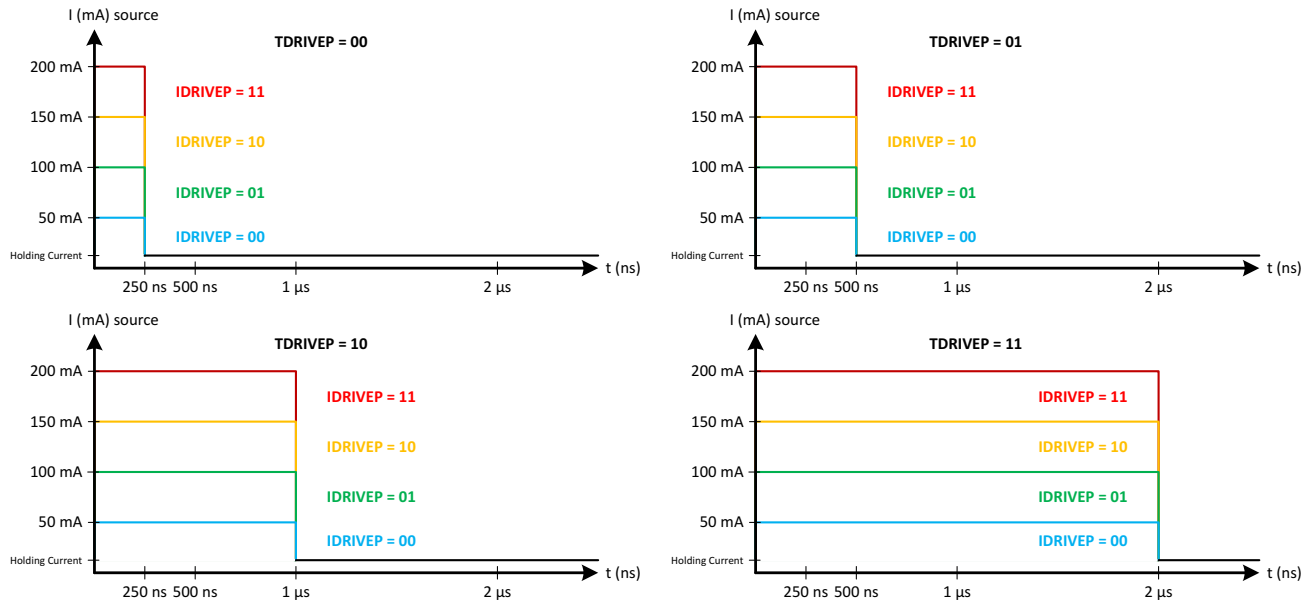
During high-side turnon, the low-side gate is pulled low. This prevents the gate-source capacitance of the low-side FET from inducing turnon.

The predriver circuits include enforcement of a dead time in analog circuitry, which prevents the high-side and low-side FETs from conducting at the same time. Additional dead time is added with digital delays. This delay can be selected by setting the DTIME bits in the CTRL register.

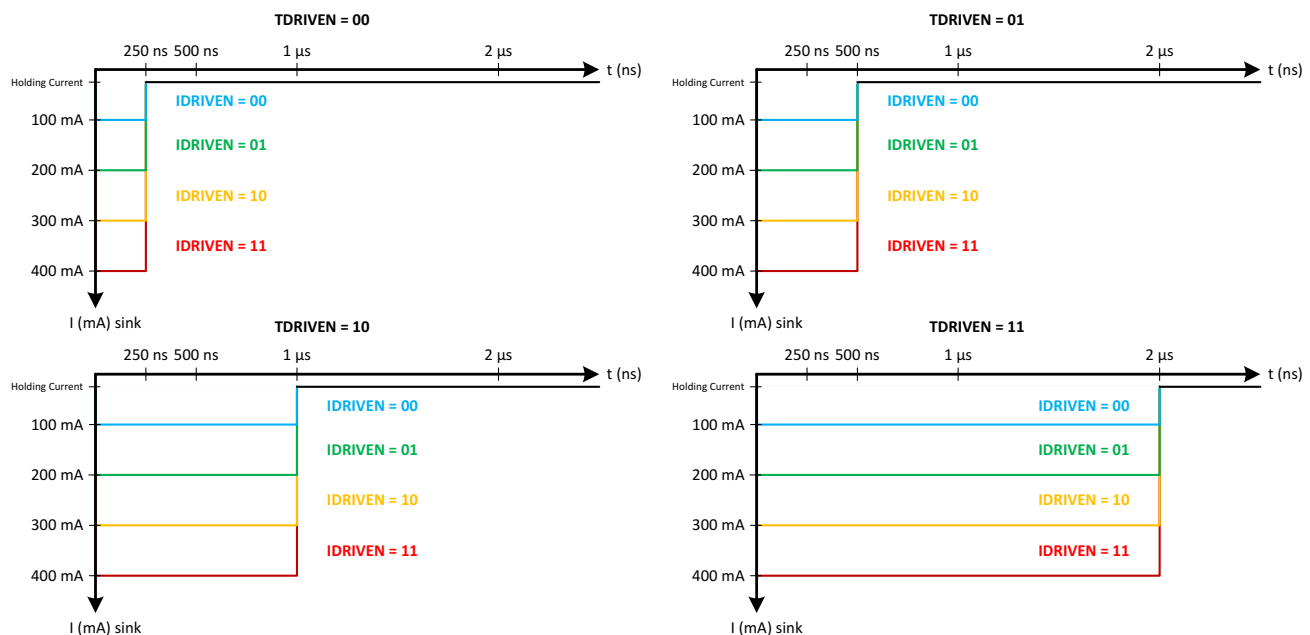


**Figure 13. Predrivers**

## Gate Pre-drive Source Capability



## Gate Pre-drive Sink Capability



**Figure 14. Gate Pre-Drive Source/Sink Capability**

### 7.3.8 Configuring Predrivers

IDRIVE and TDRIVE are selected based on the size of external FETs used. These registers need to be configured so that the FET gates are charged completely during TDRIVE. If IDRIVE and TDRIVE are chosen to be too low for a given FET, then the FET may not turn on completely. TI suggests adjusting these values in-system with the required external FETs and stepper motor to determine the best possible setting for any application.

TDRIVE will not increase the PWM time or change the PWM chopping frequency.

In a system with capacitor charge Q and desired rise time RT, IDRIVE and TDRIVE can be initially selected based on:

$$\text{IDRIVE} > Q / RT$$

$$\text{TDRIVE} > 2 \times RT$$

For best results, select the smallest IDRIVE and TDRIVE that meet the above conditions.

Example:

If the gate charge is 15 nC and the desired rise time is 400 ns, then select:

$$\text{IDRIVEP} = 50 \text{ mA}, \text{IDRIVEN} = 100 \text{ mA}$$

$$\text{TDRIVEP} = \text{TDRIVEN} = 1 \mu\text{s}$$

### 7.3.9 External FET Selection

In a typical setup, the DRV8711 can support external FETs over 50 nC each. However, this capacity can be lower or higher based on the device operation. For an accurate calculation of FET driving capacity, use the following equation.

$$Q < \frac{20\text{mA} \cdot (2 \cdot \text{DTIME} + \text{TBLANK} + \text{TOFF})}{4} \quad (3)$$

Example:

If a DTIME is set to 0 (400 ns), TBLANK is set to 0 (1 μs), and TOFF is set to 0 (500 ns), then the DRV8711 will support  $Q < 11.5 \text{ nC}$  FETs (this is an absolute worst-case scenario with a PWM frequency approximately 430 kHz).

If a DTIME is set to 0 (400 ns), TBLANK is set to 0 (1 μs), and TOFF is set to 0x14 (10 μs), then the DRV8711 will support  $Q < 59 \text{ nC}$  FETs (PWM frequency approximately 85 kHz).

If a DTIME is set to 0 (400 ns), TBLANK is set to 0 (1 μs), and TOFF is set to 0x60 (48 μs), then the DRV8711 will support  $Q < 249 \text{ nC}$  FETs (PWM frequency approximately 20 kHz).

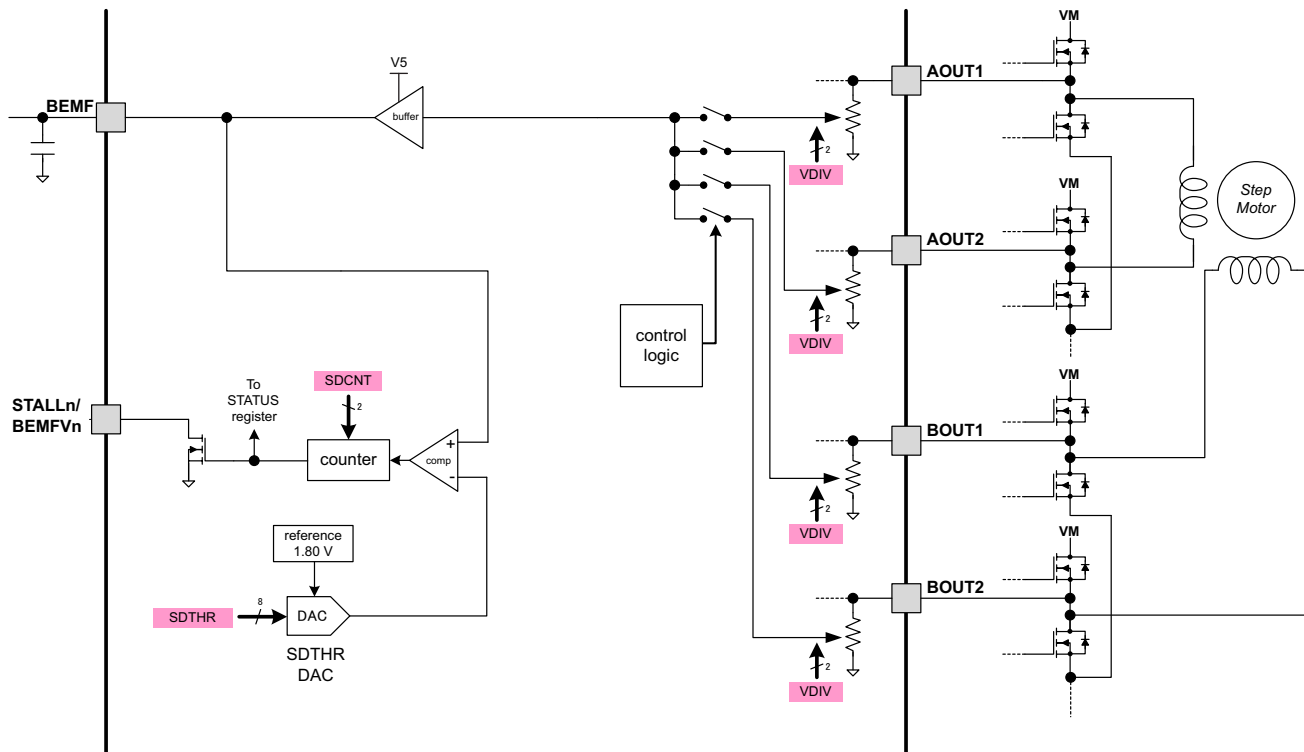
### 7.3.10 Stall Detection

The DRV8711 implements a back EMF monitoring scheme that is capable of detecting a stall during stepper motor motion. This stall detection is intended to be used to get an indication when a motor is run into a mechanical stop, or when an increased torque load on the motor causes it to stall.

To determine that a stall has occurred, a drop in motor back EMF is detected. The DRV8711 supports two methods of this detection: an automatic internal stall detection circuit, or the ability to use an external microcontroller to monitor back EMF.

During a zero-current step, one side of the H-bridge is placed in a high impedance state, and the opposite low-side FET is turned on for a brief duration defined by TORQUE register SMPLTH bit [10:8]. This allows the current to decay quickly through the low-side FET and the opposite body diode. Which side of the bridge is tri-state and which one is driven low depends on the current direction on the previous step. The bridge with the high side that has been actively PWMed (at the beginning of the PWM cycle during blank time) before entering the zero-current step will be held low and the opposite side will be tri-stated.

Back EMF is sampled on the tri-stated output pin at the end of SMPLTH time (TORQUE register bit [10:8]). The back EMF from the selected pin is divided by 4, 8, 16, or 32, depending on the setting of the VDIV bits in the STALL register. The voltage is buffered and held on an external capacitor placed on the BEMF pin. The signal on the BEMF output pin can be further processed by a microcontroller to implement more advanced control and stall detection algorithms.



**Figure 15. Stall Detection**

### 7.3.10.1 Internal Stall Detection

To use internal stall detection, the EXSTALL bit in the CTRL register is set to 0. In this mode, the STALLn/BEMFVn output pin is used to signal a valid stall condition.

Step time, or rate at which step input is applied to DRV8711, has to be greater than SMPLTH time for back EMF sampling.

Using internal stall detection, a stall is detected when the sampled back EMF drops below the value set by the SDTHR bits in the STALL register. A programmable counter circuit allows the assertion of the STALLn output to be delayed until the back EMF has been sampled below the SDTHR value for more than one zero-current step. The counter is programmed by the SDCNT bits in the STALL register, and provides selections of 1, 2, 4, or 8 steps.

When the stall is detected (at the end of a SMPLTH interval), the STALLn/BEMFVn pin is driven active low, and the STD bit and the stdLAT bit in the STATUS register are set. The STALLn/BEMFVn pin will deassert and the STD bit will automatically clear at the next zero-current step if a stall condition is not detected, while the stdLAT bit will remain set until a 0 is written to it. The stdLAT is reset when the STD bit clears after the first zero-cross step that does not detect a stall condition.

This stall detection scheme is only effective when the motor is stalled while running at or above some minimum speed. Because it relies on detecting a drop in motor back EMF, the motor must be rotating with sufficient speed to generate a detectable back EMF. During motor start-up, and at very slow step rates, the stall detection is not reliable.

Because back EMF can only be sampled during a zero-current state, stall detection is not possible in full step mode. During full-step operation, the stall detect circuit is gated off to prevent false signaling of a stall.

The correct setting of the SDTHR bits needs to be determined experimentally. It is dependent on many factors, including the electrical and mechanical characteristics of the load, the peak current setting, and the supply voltage.

### **7.3.10.2 External Stall Detection**

To use an external microcontroller to manage stall detection, the EXSTALL bit in the CTRL register is set to 1. In this mode, the STALLn / BEMFVn output pin is used to signal a valid back EMF measurement is ready. In addition, the SDT and SDTLAT bits are also set at this time.

BEMFVn and BEMF are still valid outputs in this mode even if the step time is smaller than SMPLTH time.

When the BEMFVn pin goes active low, it is an indication that a valid back EMF voltage measurement is available. This signal could be used, for example, to trigger an interrupt on a microcontroller. The microcontroller can then sample the voltage present (using an A/D converter) on the BEMF pin.

After sampling the back EMF voltage, the microcontroller writes a 0 to the SDTLAT bit to clear the SDT bit and BEMFVn pin, in preparation for the next back EMF sample. If the SDTLAT bit is not cleared by the microcontroller, it will automatically be cleared in the next zero-current step.

For either internal or external stall detection, at very high motor speeds when the PWM duty cycle approaches 100%, the inductance of the motor and the short duration of each step may cause the time required for current recirculation to exceed the step time. In this case, back EMF will not be correctly sampled, and stall detection cannot function. This condition occurs most at high degrees of micro-stepping, because the zero current step lasts for a shorter duration. It is advisable to run the motor at lower degrees of micro-stepping at higher speeds to allow time for current recirculation if stall detection is needed in this condition.

### **7.3.11 Protection Circuits**

The DRV8711 is fully protected against undervoltage, overcurrent and overtemperature events.

#### **7.3.11.1 Overcurrent Protection (OCP)**

Overcurrent is sensed by monitoring the voltage drop across the external FETs. If the voltage across a driven FET exceeds the value programmed by the OCPH bits in the DRIVE register for more than the time period specified by the OCPDEG bits in the DRIVE register, an OCP event is recognized. When operating in direct PWM mode, during an OCP event, the H-bridge experiencing the OCP event is disabled; if operating in indexer mode, both H-bridges will be disabled. In addition, the corresponding xOCP bit in the STATUS register is set, and the FAULTn pin is driven low. The H-bridge(s) will remain off, and the xOCP bit will remain set, until it is written to 0, or the device is reset.

#### **7.3.11.2 Predriver Fault**

In PWM mode, if excessive current is detected on the gate drive outputs (which would be indicative of a failed/shorted output FET or PCB fault), the H-bridge experiencing the fault is disabled, the xPDF bit in the STATUS register is set, and the FAULTn pin is driven low. The H-bridge will remain off, and the xPDF bit will remain set until it is written to 0 or the device is reset.

When in indexer mode, both H-bridges are disabled, the xPDF bit in the STATUS register is set, and the FAULTn pin is driven low. The H-bridges will remain off, and the xPDF bit will remain set until it is written to 0 or the device is reset.

#### **7.3.11.3 Thermal Shutdown (TSD)**

If the die temperature exceeds safe limits, all FETs in the H-bridge will be disabled, the OTS bit in the STATUS register will be set, and the FAULTn pin will be driven low. Once the die temperature has fallen to a safe level operation will automatically resume and the OTS bit will reset. The FAULTn pin will be released after operation has resumed.

#### **7.3.11.4 Undervoltage Lockout (UVLO)**

If at any time the voltage on the VM pin falls below the undervoltage lockout threshold voltage, all FETs in the H-bridge will be disabled, the UVLO bit in the STATUS register will be set, and the FAULTn pin will be driven low. Operation will resume and the UVLO bit will reset when VM rises above the UVLO threshold. The FAULTn pin will be released after operation has resumed.

During any of these fault conditions, the STEP input pin will be ignored.



## 7.4 Device Functional Modes

### 7.4.1 RESET and SLEEPn Operation

An internal power-up reset circuit monitors the voltage applied to the VM pin. If VM falls below the VM undervoltage lockout voltage, the part is reset, as described below for the case of asserting the RESET pin.

If the RESET pin is asserted, all internal logic including the indexer is reset. All registers are returned to their initial default conditions. The power stage will be disabled, and all inputs, including STEP and the serial interface, are ignored when RESET is active.

On exiting reset state, some time (approximately 1 mS) needs to pass before the part is fully functional.

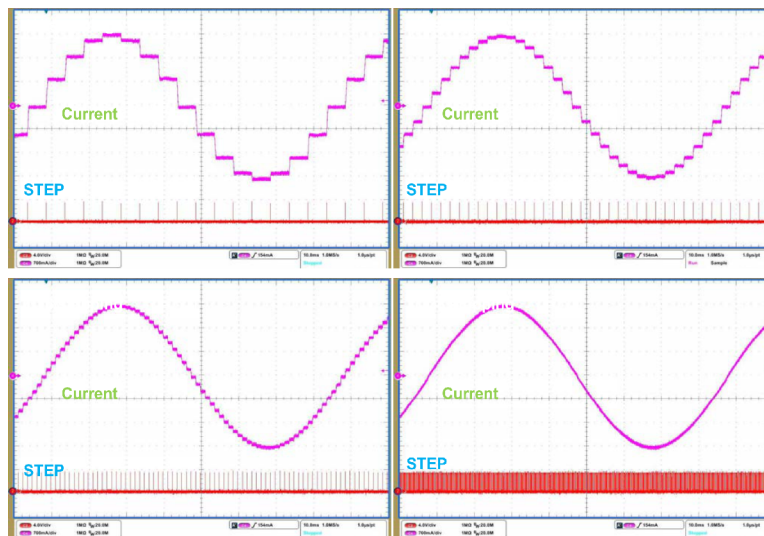
Applying an active low input to the SLEEPn input pin will place the device into a low power state. In sleep mode, the motor driver circuitry is disabled, the gate drive regulator and charge pump are disabled, and all analog circuitry is placed into a low power state. The digital circuitry in the device still operates, so the device registers can still be accessed via the serial interface.

When SLEEPn is active, the RESET pin does not function. SLEEPn must be exited before RESET will take effect.

When exiting from sleep mode, some time (approximately 1 mS) needs to pass before applying a STEP input, to allow the internal circuitry to stabilize.

### 7.4.2 Microstepping Drive Current

Figure 16 shows examples of stepper motor current in one of the windings. Because these waveforms are dependent on DRV8711 register settings as well as the external FETs, sense resistor, and stepper motor, they should only be used as a reference.



**Figure 16. Microstepping Drive Current**

## 7.5 Programming

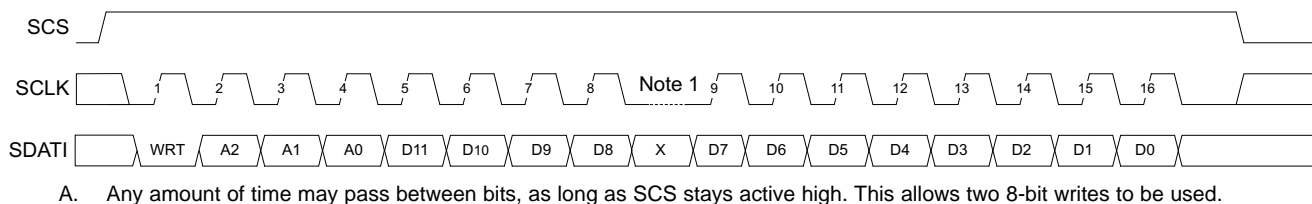
### 7.5.1 Serial Data Format

The serial data consists of a 16-bit serial write, with a read/write bit, 3 address bits and 12 data bits. The 3 address bits identify one of the registers defined in the register section above. To complete the read or write transaction, SCS must be set to a logic 0.

To write to a register, data is shifted in after the address as shown in the timing diagram below. The first bit at the beginning of the access must be logic low for a write operation.

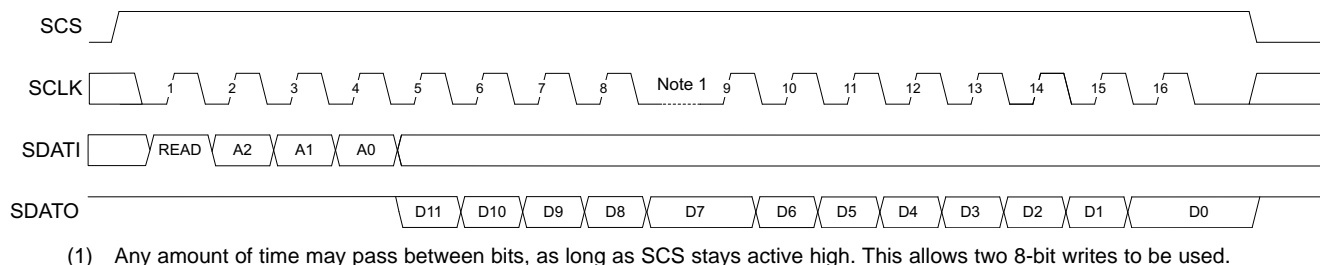


## Programming (continued)



**Figure 17. Write Operation**

Data may be read from the registers through the SDATO pin. During a read operation, only the address is used from the SDATI pin; the data bits following are ignored. The first bit at the beginning of the access must be logic high for a read operation.



**Figure 18. Read Operation**

## 7.6 Register Maps

### 7.6.1 Control Registers

The DRV8711 uses internal registers to control the operation of the motor. The registers are programmed through a serial SPI communications interface. At power up or reset, the registers will be preloaded with default values as shown in [CTRL Register Address = 0x0h](#) to [STATUS Register Address = 0x7h](#).

[Figure 19](#) is a map of the DRV8711 registers.

Individual register contents are defined in [CTRL Register Address = 0x0h](#) to [STATUS Register Address = 0x7h](#).

DRV8711 REGISTER MAP															
Name	11	10	9	8	7	6	5	4	3	2	1	0		Address Hex	
CTRL	DTIME		ISGAIN		EXSTALL	MODE				RSTEP		RDIR	ENBL	RW	00
TORQUE	Reserved	SMPLTH			TORQUE								RW	01	
OFF	Reserved			PWMODE	TOFF								RW	02	
BLANK	Reserved			ABT	TBLANK								RW	03	
DECAY	Reserved	DECMOD			TDECAY								RW	04	
STALL	VDIV		SDCNT		SDTHR								RW	05	
DRIVE	IDRIVEP		IDRIVEN		TDRIVEP		TDRIVEN		OCPDEG		OCPH		RW	06	
STATUS	Reserved				STDLAT	STD	UVLO	BPDF	APDF	BOCP	AOCP	OTS	RW	07	
Name	11	10	9	8	7	6	5	4	3	2	1	0		Address Hex	

**Figure 19. DRV8711 Register Map**

## Register Maps (continued)

### 7.6.2 CTRL Register Address = 0x0h

BIT	NAME	SIZE	R/W	DEFAULT	DESCRIPTION
0	ENBL	1	R/W	0	<b>0: Disable motor</b> 1: Enable motor
1	RDIR	1	R/W	0	<b>0: Direction set by DIR pin</b> 1: Direction set by inverse of DIR pin
2	RSTEP	1	W	0	0: No action 1: Indexer will advance one step; automatically cleared after write
6-3	MODE	4	R/W	0010	0000: Full-step, 71% current 0001: Half step <b>0010: 1/4 step</b> 0011: 1/8 step 0100: 1/16 step 0101: 1/32 step 0110: 1/64 step 0111: 1/128 step 1000: 1/256 step 1001 – 1111: Reserved
7	EXSTALL	1	R/W	0	<b>0: Internal stall detect</b> 1: External stall detect
9-8	ISGAIN	2	R/W	00	ISENSE amplifier gain set <b>00: Gain of 5</b> 01: Gain of 10 10: Gain of 20 11: Gain of 40
11-10	DTIME	2	R/W	11	Dead time set 00: 400 ns dead time 01: 450 ns dead time 10: 650 ns dead time <b>11: 850 ns dead time</b>

### 7.6.3 TORQUE Register Address = 0x1h

BIT	NAME	SIZE	R/W	DEFAULT	DESCRIPTION
7-0	TORQUE	8	R/W	0xFFh	Sets full-scale output current for both H-bridges
10-8	SMPLTH	3	R/W	001	Back EMF sample threshold 000: 50 $\mu$ s <b>001: 100 <math>\mu</math>s</b> 010: 200 $\mu$ s 011: 300 $\mu$ s 100: 400 $\mu$ s 101: 600 $\mu$ s 110: 800 $\mu$ s 111: 1000 $\mu$ s
11	Reserved	1	-	-	Reserved

### 7.6.4 OFF Register Address = 0x2h

BIT	NAME	SIZE	R/W	DEFAULT	DESCRIPTION
7-0	TOFF	8	R/W	0x30h	Sets fixed off time, in increments of 500 ns 0x00h: 500 ns 0xFFh: 128 $\mu$ s
8	PWMODE	1	R/W	0	<b>0: Use internal indexer</b> 1: Bypass indexer, use xINx inputs to control outputs
11-9	Reserved	3	-	-	Reserved

### 7.6.5 BLANK Register Address = 0x3h

BIT	NAME	SIZE	R/W	DEFAULT	DESCRIPTION
7-0	TBLANK	8	R/W	0x80h	Sets current trip blanking time, in increments of 20 ns 0x00h: 1 $\mu$ s ... 0x32h: 1 $\mu$ s 0x33h: 1.02 $\mu$ s ... 0xFEh: 5.10 $\mu$ s 0xFFh: 5.12 $\mu$ s Also sets minimum on-time of PWM
8	ABT	1	R/W	0	<b>0: Disable adaptive blanking time</b> 1: Enable adaptive blanking time
11-9	Reserved	3	-	-	Reserved

### 7.6.6 DECAY Register Address = 0x4h

BIT	NAME	SIZE	R/W	DEFAULT	DESCRIPTION
7-0	TDECAY	8	R/W	0x10h	Sets mixed decay transition time, in increments of 500 ns
10-8	DECMOD	3	R/W	001	000: Force slow decay at all times <b>001: Slow decay for increasing current, mixed decay for decreasing current (indexer mode only)</b> 010: Force fast decay at all times 011: Use mixed decay at all times 100: Slow decay for increasing current, auto mixed decay for decreasing current (indexer mode only) 101: Use auto mixed decay at all times 110 – 111: Reserved
11	Reserved	1	-	-	Reserved

### 7.6.7 STALL Register Address = 0x5h

BIT	NAME	SIZE	R/W	DEFAULT	DESCRIPTION
7-0	SDTHR	8	R/W	0x40h	Sets stall detect threshold The correct setting needs to be determined experimentally
9-8	SDCNT	2	R/W	00	<b>00: STALLn asserted on first step with back EMF below SDTHR</b> 01: STALLn asserted after 2 steps 10: STALLn asserted after 4 steps 11: STALLn asserted after 8 steps
11-10	VDIV	2	R/W	00	<b>00: Back EMF is divided by 32</b> 01: Back EMF is divided by 16 10: Back EMF is divided by 8 11: Back EMF is divided by 4

### 7.6.8 DRIVE Register Address = 0x6h

BIT	NAME	SIZE	R/W	DEFAULT	DESCRIPTION
1-0	OCPH	2	R/W	00	OCP threshold <b>00: 250 mV</b> 01: 500 mV 10: 750 mV 11: 1000 mV
3-2	OCPDEG	2	R/W	01	OCP deglitch time 00: 1 $\mu$ s <b>01: 2 <math>\mu</math>s</b> 10: 4 $\mu$ s 11: 8 $\mu$ s
5-4	TDRIVEN	2	R/W	01	Low-side gate drive time 00: 250 ns <b>01: 500 ns</b> 10: 1 $\mu$ s 11: 2 $\mu$ s

**DRV8711**

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[www.ti.com](http://www.ti.com)

BIT	NAME	SIZE	R/W	DEFAULT	DESCRIPTION
7-6	TDRIVEP	2	R/W	01	High-side gate drive time 00: 250 ns <b>01: 500 ns</b> 10: 1 $\mu$ s 11: 2 $\mu$ s
9-8	IDRIVEN	2	R/W	00	Low-side gate drive peak current <b>00: 100 mA peak (sink)</b> 01: 200 mA peak (sink) 10: 300 mA peak (sink) 11: 400 mA peak (sink)
11-10	IDRIVEP	2	R/W	00	High-side gate drive peak current <b>00: 50 mA peak (source)</b> 01: 100 mA peak (source) 10: 150 mA peak (source) 11: 200 mA peak (source)

**7.6.9 STATUS Register Address = 0x7h**

BIT	NAME	SIZE	R/W	DEFAULT	DESCRIPTION
0	OTS	1	R	0	0: Normal operation 1: Device has entered overtemperature shutdown OTS bit will clear once temperature has fallen to safe levels
1	AOCP	1	R/W	0	0: Normal operation 1: Channel A overcurrent shutdown Write a '0' to this bit to clear the fault and resume operation
2	BOCP	1	R/W	0	0: Normal operation 1: Channel B overcurrent shutdown Write a '0' to this bit to clear the fault and resume operation
3	APDF	1	R/W	0	0: Normal operation 1: Channel A predriver fault Write a '0' to this bit to clear the fault and resume operation
4	BPDF	1	R/W	0	0: Normal operation 1: Channel B predriver fault Write a '0' to this bit to clear the fault and resume operation
5	UVLO	1	R	0	0: Normal operation 1: Undervoltage lockout UVLO bit will clear after VM has increased over $V_{UVLO}$
6	STD	1	R	0	0: Normal operation 1: Stall detected
7	STDLAT	1	R/W	0	0: Normal operation 1: Latched stall detect Write a '0' to this bit to clear the fault and resume operation
11-8	Reserved	4	-	-	Reserved

## 8 Applications and Implementation

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The DRV8711 is used in bipolar stepper control. The microstepping motor predriver provides additional precision and a smooth rotation from the stepper motor.

#### 8.1.1 Sense Resistor

For optimal performance, it is important for the sense resistor to be:

- Surface-mount
- Low inductance
- Rated for high enough power
- Placed closely to the motor driver

The power dissipated by the sense resistor equals  $I_{\text{RMS}}^2 \times R$ . For example, if peak motor current is 3 A, RMS motor current is 2 A, and a 0.05-Ω sense resistor is used, the resistor will dissipate  $2 \text{ A}^2 \times 0.05 \text{ } \Omega = 0.2 \text{ W}$ . The power quickly increases with higher current levels.

Resistors typically have a rated power within some ambient temperature range, along with a derated power curve for high ambient temperatures. When a PCB is shared with other components generating heat, margin should be added. It is always best to measure the actual sense resistor temperature in a final system, along with the power MOSFETs, as those are often the hottest components.

Because power resistors are larger and more expensive than standard resistors, it is common practice to use multiple standard resistors in parallel, between the sense node and ground. This distributes the current and heat dissipation.

#### 8.1.2 Optional Series Gate Resistor

In high current or high voltage applications, the low side predriver fault may assert due to noise in the system. In this application, TI recommends placing a 47 to 120-Ω resistor in series with the low side output and the gate of the low side FET. TI also recommends setting the dead time to 850 ns when adding a series resistor.

### 8.2 Typical Application

The following design is a common application of the DRV8711.



## 8.2.2 Detailed Design Procedure

### 8.2.2.1 Stepper Motor Speed

The first step in configuring the DRV8711 requires the desired motor speed and microstepping level. If the target application requires a constant speed, then a square wave with frequency  $f_{\text{step}}$  must be applied to the STEP pin.

If the target motor start-up speed is too high, the motor will not spin. Make sure that the motor can support the target speed or implement an acceleration profile to bring the motor up to speed.

For a desired motor speed ( $V$ ), microstepping level ( $n_m$ ), and motor full step angle ( $\theta_{\text{step}}$ ),

$$f_{\text{step}} (\mu\text{steps/second}) = \frac{V \left( \frac{\text{rotations}}{\text{minute}} \right) \times 360 \left( \frac{^\circ}{\text{rotation}} \right) \times n_m \left( \frac{\mu\text{steps}}{\text{step}} \right)}{60 \left( \frac{\text{seconds}}{\text{minute}} \right) \times \theta_{\text{step}} \left( \frac{^\circ}{\text{step}} \right)} \quad (4)$$

$$f_{\text{step}} (\mu\text{steps/second}) = \frac{120 \left( \frac{\text{rotations}}{\text{minute}} \right) \times 360 \left( \frac{^\circ}{\text{rotation}} \right) \times 8 \left( \frac{\mu\text{steps}}{\text{step}} \right)}{60 \left( \frac{\text{seconds}}{\text{minute}} \right) \times 1.8 \left( \frac{^\circ}{\text{step}} \right)} \quad (5)$$

$\theta_{\text{step}}$  can be found in the stepper motor data sheet or written on the motor itself.

For the DRV8711, the microstepping level is set by the MODE bits in the CTRL register. Higher microstepping will mean a smoother motor motion and less audible noise, but will increase switching losses and require a higher  $f_{\text{step}}$  to achieve the same motor speed.

### 8.2.2.2 Current Regulation

In a stepper motor, the set full-scale current ( $I_{\text{FS}}$ ) is the maximum current driven through either winding. For the DRV8711, this quantity will depend on the analog voltage, the programmed torque and gain values, and the sense resistor value ( $R_{\text{SENSE}}$ ). During stepping, IFS defines the current chopping threshold ( $I_{\text{TRIP}}$ ) for the maximum current step. The gain of DRV8711 is set for 5 V/V.

$$I_{\text{FS}} (\text{A}) = \frac{2.75 (\text{V}) \times \text{TORQUE}}{256 \times \text{ISGAIN} \times R_{\text{SENSE}} (\Omega)} \quad (6)$$

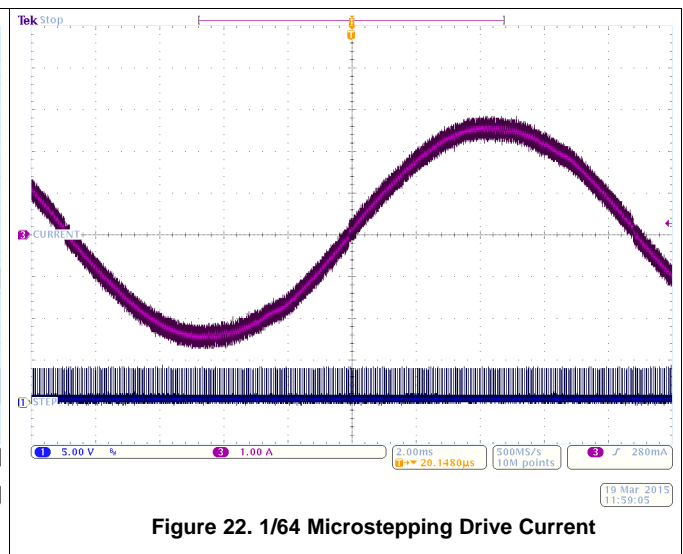
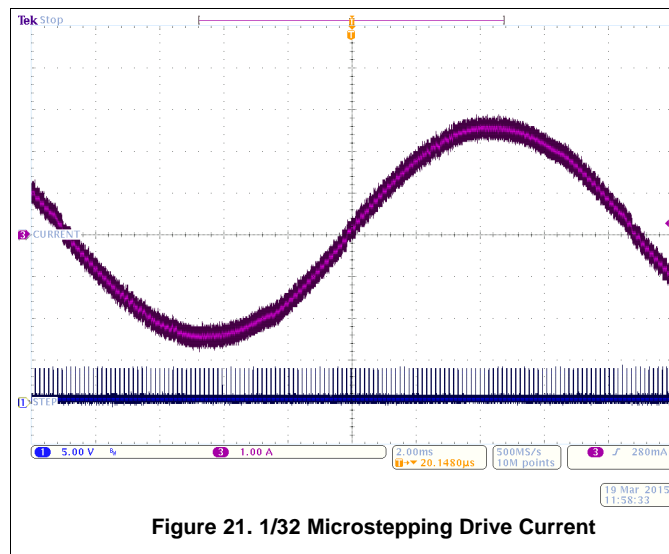
To achieve  $I_{\text{FS}} = 1.25 \text{ A}$  with  $R_{\text{SENSE}}$  of  $0.2 \Omega$  with a gain of 5, TORQUE should be set to 116(dec).

### 8.2.2.3 Decay Modes

The DRV8711 supports three different decay modes: slow decay, fast decay, and mixed decay. The DRV8711 also supports automatic mixed decay mode, which minimizes current ripple. The current through the motor windings is regulated using programmable settings for blanking, decay and off time. This means that after any drive phase, when a motor winding current has hit the current chopping threshold ( $I_{\text{TRIP}}$ ), the DRV8711 will place the winding in the programmed decay modes until the cycle has expired. Afterward, a new drive phase starts.

The blanking time  $T_{\text{BLANK}}$  defines the minimum drive time for the current chopping.  $I_{\text{TRIP}}$  is ignored during  $T_{\text{BLANK}}$ , so the winding current may overshoot the trip level.

## 8.2.3 Application Curves





## 9 Power Supply Recommendations

### 9.1 Bulk Capacitance

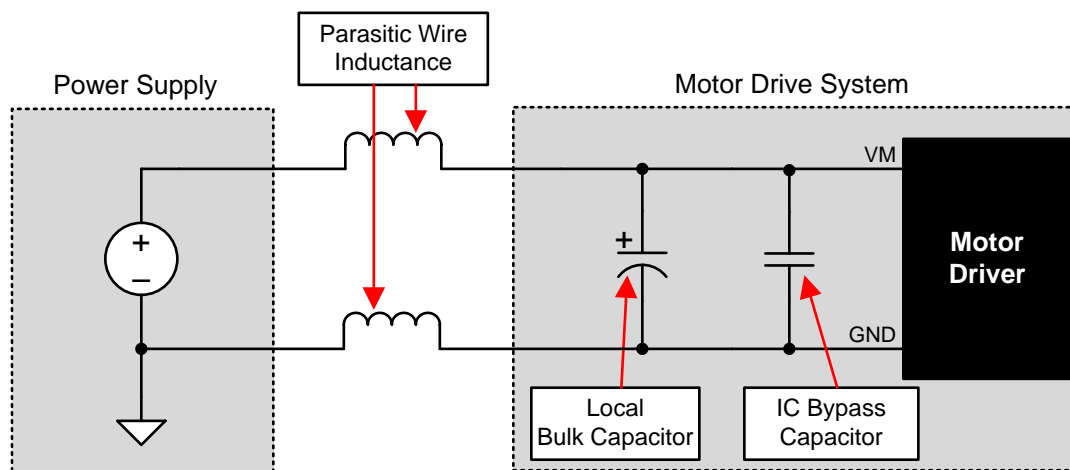
Having an appropriate local bulk capacitance is an important factor in motor drive system design. It is generally beneficial to have more bulk capacitance, while the disadvantages are increased cost and physical size.

The amount of local capacitance needed depends on a variety of factors, including:

- The highest current required by the motor system
- The power supply's capacitance and ability to source current
- The amount of parasitic inductance between the power supply and motor system
- The acceptable voltage ripple
- The type of motor used (Brushed DC, Brushless DC, Stepper)
- The motor braking method

The inductance between the power supply and the motor drive system limits the rate current can change from the power supply. If the local bulk capacitance is too small, the system responds to excessive current demands or dumps from the motor with a change in voltage. When adequate bulk capacitance is used, the motor voltage remains stable and high current can be quickly supplied.

The data sheet generally provides a recommended value, but system-level testing is required to determine the appropriate sized bulk capacitor.



**Figure 23. Example Setup of Motor Drive System With External Power Supply**

The voltage rating for bulk capacitors should be higher than the operating voltage, to provide margin for cases when the motor transfers energy to the supply.

## 10 Layout

### 10.1 Layout Guidelines

The VM pin should be bypassed to GND using low-ESR ceramic bypass capacitors with a recommended value of 0.01- $\mu$ F rated for VM. This capacitor should be placed as close to the VM pin as possible with a thick trace or ground plane connection to the device GND pin. The VM pin must be bypassed to ground using an appropriate bulk capacitor. This component may be an electrolytic and should be located close to the DRV8711.

A low-ESR ceramic capacitor must be placed in between the VM and VCP pins. TI recommends a value of 1  $\mu$ F rated for 16 V. Place this component as close to the pins as possible.

A low-ESR ceramic capacitor must be placed in between the CP1 and CP2 pins. TI recommends a value of 0.1  $\mu$ F rated for VM. Place this component as close to the pins as possible.

Bypass VINT to ground with a 1- $\mu$ F ceramic capacitor rated 6.3 V. Place this bypass capacitor as close to the pin as possible.

Bypass V5 to ground with a 1- $\mu$ F ceramic capacitor rated 10 V. Place this bypass capacitor as close to the pin as possible.

## 10.2 Layout Example

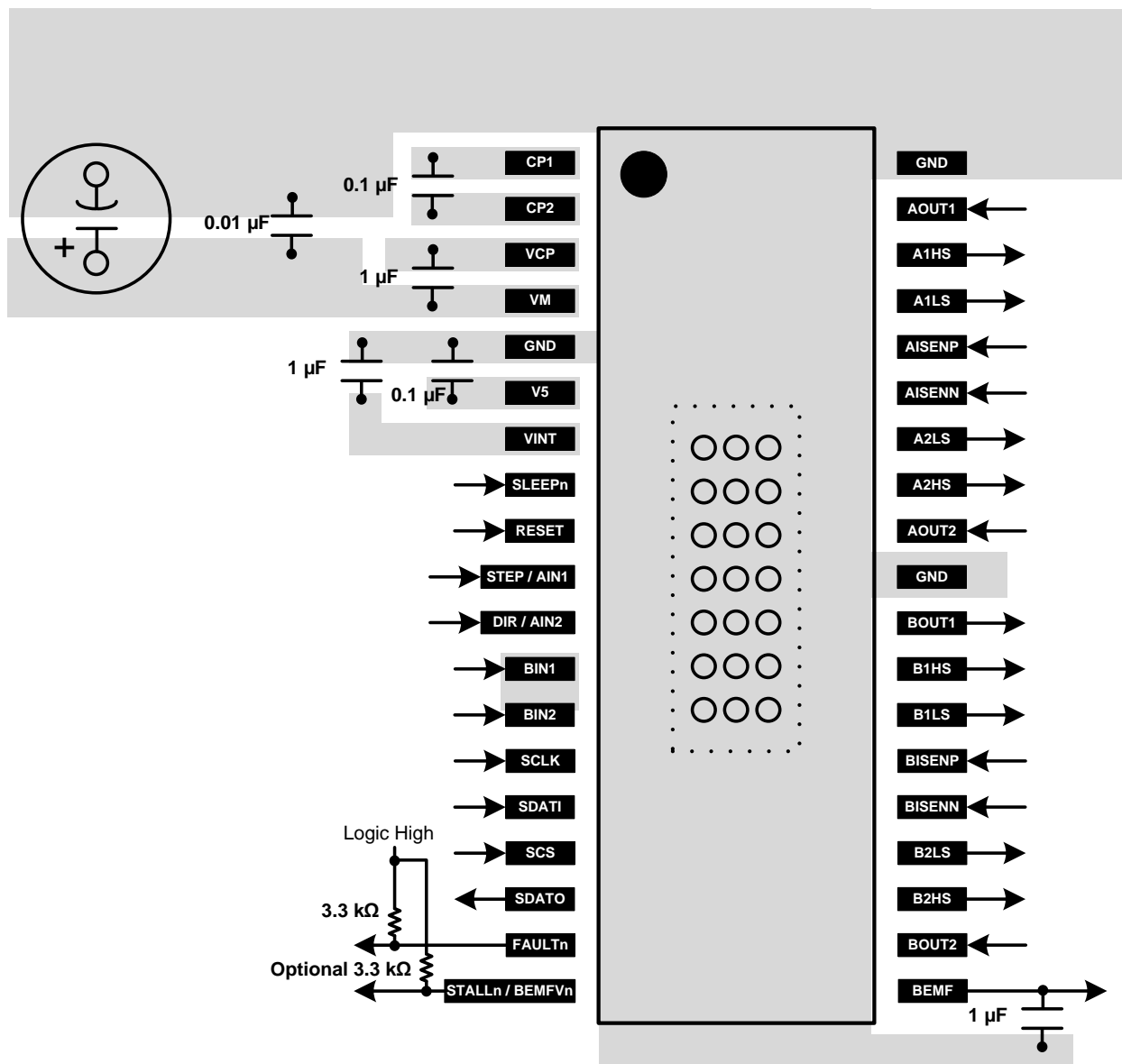


Figure 24. Recommended Layout Example

## 11 Device and Documentation Support

### 11.1 Documentation Support

#### 11.1.1 Related Documentation

For related documentation see the following:

- *DRV8711 Decay Mode Setting Optimization*, [SLVA637](#)
- *DRV8711 Quick Spin and Tuning Guide*, [SLVA632](#)
- *PowerPAD™ Thermally Enhanced Package*, [SLMA002](#)
- *PowerPAD™ Made Easy*, [SLMA004](#)

#### 11.2 Trademarks

PowerPAD is a trademark of Texas Instruments.  
All other trademarks are the property of their respective owners.

#### 11.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

#### 11.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
DRV8711DCP	ACTIVE	HTSSOP	DCP	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	DRV8711	<a href="#">Samples</a>
DRV8711DCPR	ACTIVE	HTSSOP	DCP	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	DRV8711	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DRV8711DCPR	HTSSOP	DCP	38	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

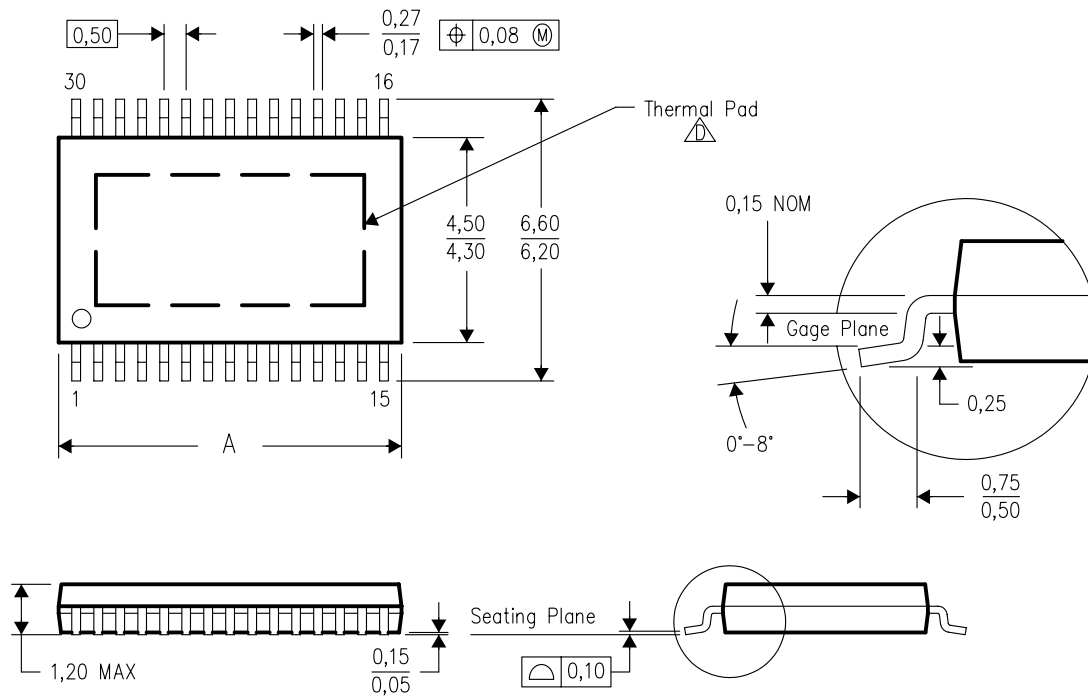
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DRV8711DCPR	HTSSOP	DCP	38	2000	367.0	367.0	38.0



DCP (R-PDSO-G\*\*)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE

30 PIN SHOWN



PINS **	28	30	38	44	50
DIM					
A MAX	7,90	7,90	9,80	11,40	12,60
A MIN	7,70	7,70	9,60	11,20	12,40

4073267/C 03/05

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusions, mold flash not to exceed 0.15mm.
  - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at [www.ti.com](http://www.ti.com). See the product data sheet for details regarding the exposed thermal pad dimensions.
  - E. Falls within JEDEC MO-153

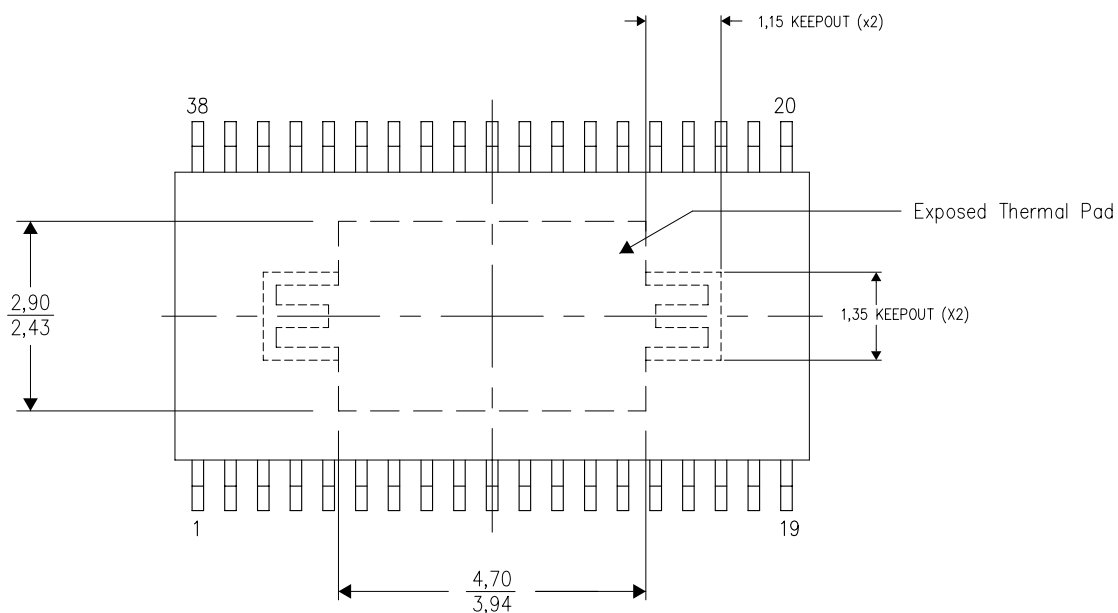
PowerPAD is a trademark of Texas Instruments.

## THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.

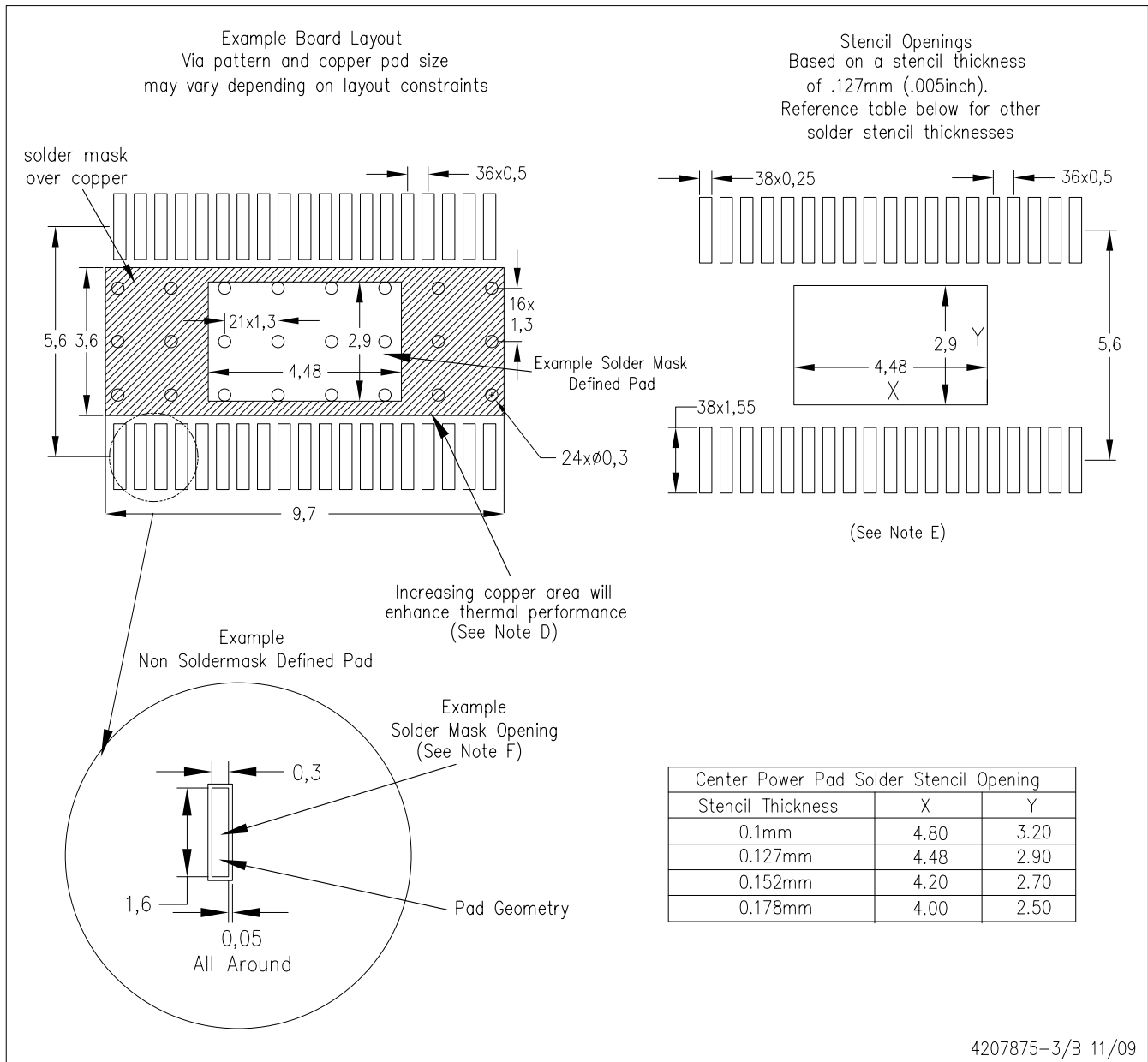


Top View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

## DCP (R-PDSO-G38) PowerPAD™



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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